

TOOLS FOR RELIABILITY MODELING AND CHARACTERIZATION OF FERROELECTRIC DEVICES

IUNET-UNIMORE



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- **Ferroelectric Polarization**
 - Incomplete Compensation
 - Depolarization Dynamics
- **Reliability Issues in Ferroelectrics**
 - Endurance and Aging
 - Retention
 - Imprint
- **Tools for Reliability Characterization and Modeling**
 - Backswitching Measurements
 - FORC/URC/D-URC Measurements
 - Impedance Spectroscopy
 - Advanced Physics-based Simulations



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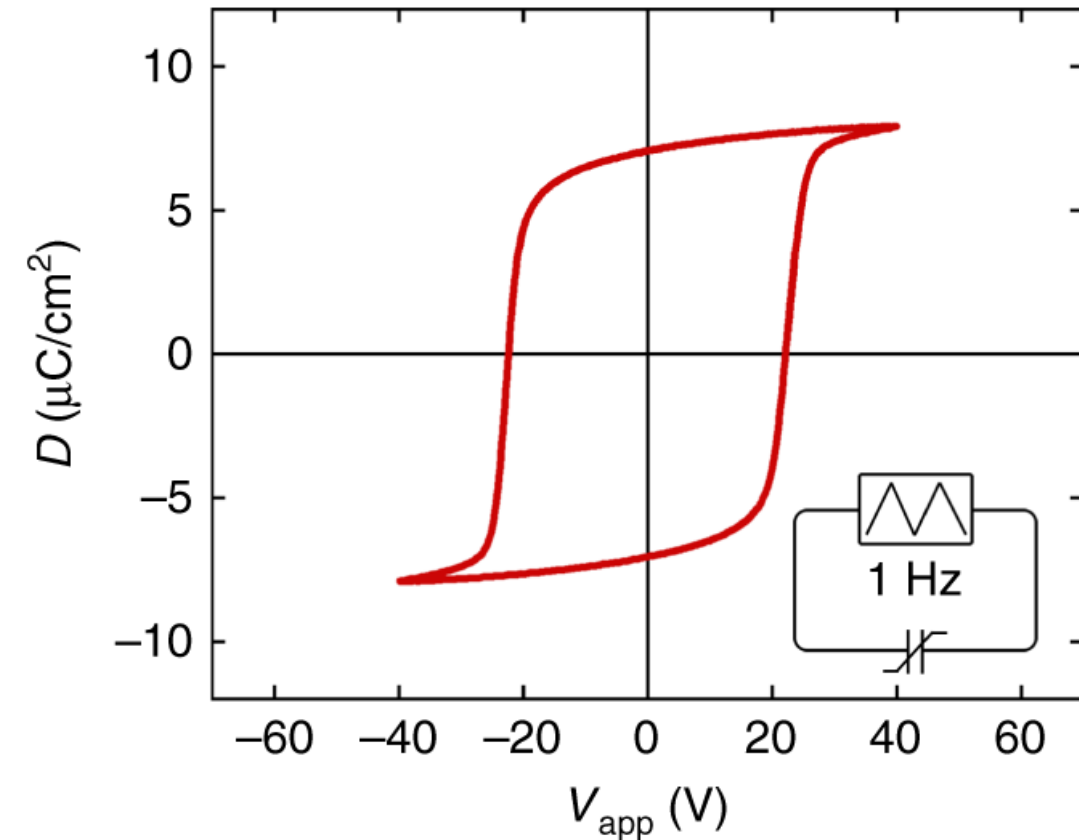
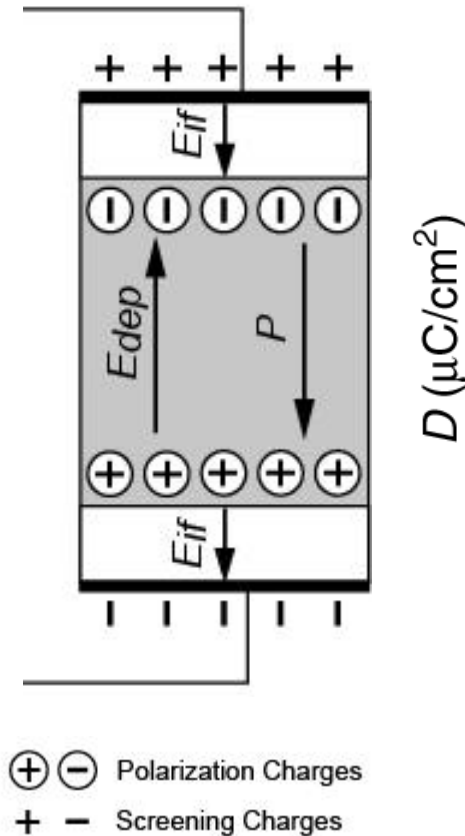
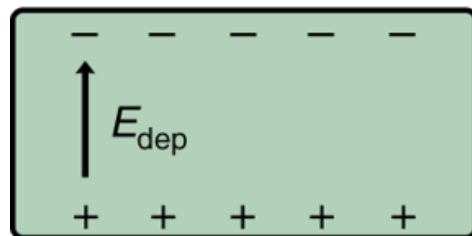


- **Reversible spontaneous polarization**

- Allows polarization switching ☺
- Implies depolarization field ☹

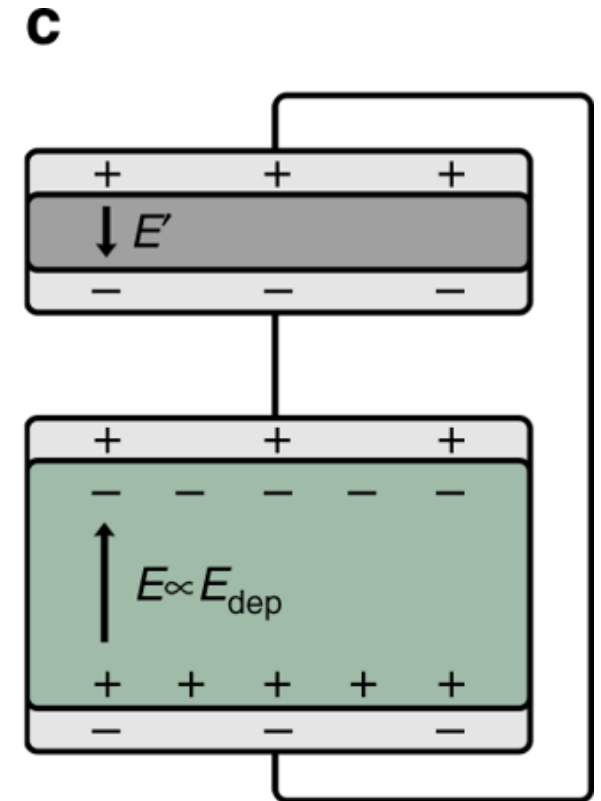
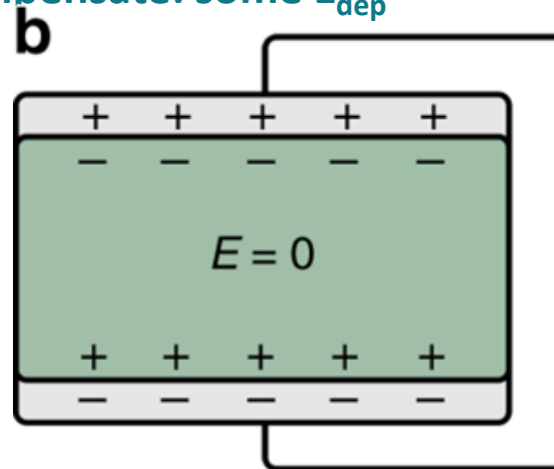
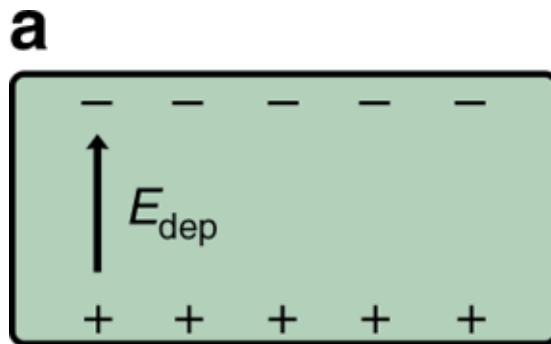
- **D-V measurements let us get**

- Coercive Field(s)/Voltage(s)
- Saturation Polarization(s)
- Remnant Polarization(s)
- Relative Permittivity
- Frequency Dependence



D. Zhao et al., Nat Commun 10, 2547 (2019)

- What happens in case of incomplete compensation:
 - Ferroelectric slab (a): No compensation
 - No free charge can compensate: highest E_{dep}
 - MFM capacitor (b): Complete compensation
 - Free charge can completely compensate: no E_{dep}
 - MFM + Series capacitor or MDFM (c): Partial compensation
 - Free charge can partially compensate: some E_{dep}



D. Zhao et al., Nat Commun 10, 2547 (2019)

INCOMPLETE COMPENSATION

FIXIT

Some math shows what we can measure and calculate (case c)

- Measuring D allows calculating:
 - Voltage on the ferroelectric
 - Electric field in the ferroelectric
 - Polarization

KVL $\longrightarrow V_{\text{app}} = V_{\text{ferro}} + V_{\text{ser}}$

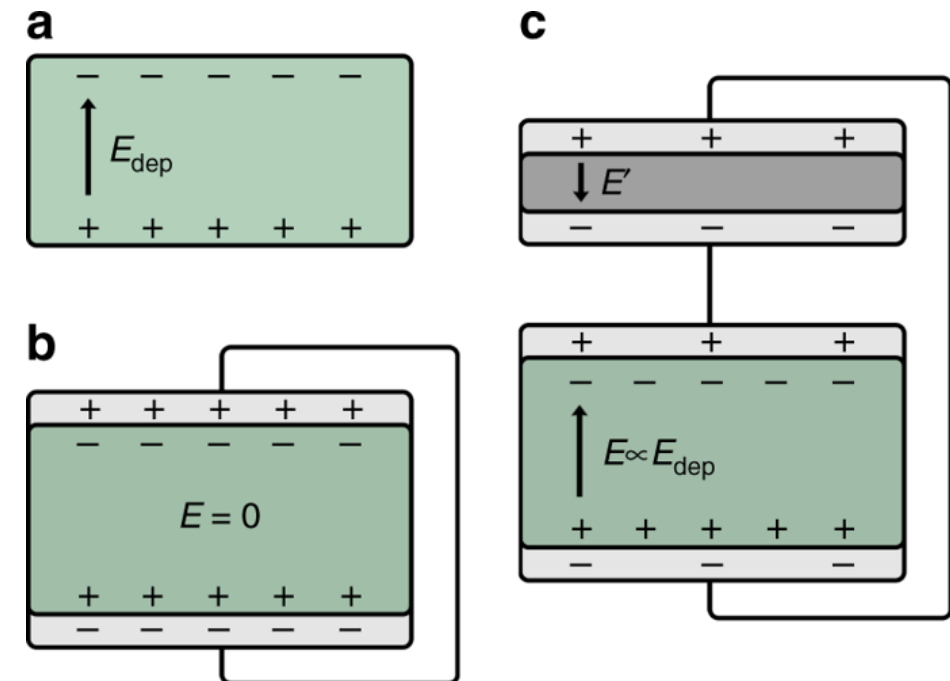
$$V_{\text{ferro}} = \frac{Q_{\text{ferro}} - PA}{C_{\text{ferro}}} \quad V_{\text{ferro}} = V_{\text{app}} - \frac{Q_{\text{ser}}}{C_{\text{ser}}}$$

Charge continuity $\longrightarrow Q_{\text{ferro}} = Q_{\text{ser}} = V_{\text{ferro}} C_{\text{ferro}} + PA$

$$V_{\text{ferro}} = \frac{C_{\text{ser}}}{C_{\text{ser}} + C_{\text{ferro}}} V_{\text{app}} - \frac{PA}{C_{\text{ser}} + C_{\text{ferro}}}$$

Electrostatics $\longrightarrow D = \frac{\epsilon_0 \epsilon_{\text{ferro}} V_{\text{ferro}}}{d} + P$

$$E_{\text{ferro}} = \frac{V_{\text{app}}}{d} - \frac{D}{\epsilon_0 \epsilon_{\text{ferro}}} \cdot \frac{C_{\text{ferro}}}{C_{\text{ser}}}$$

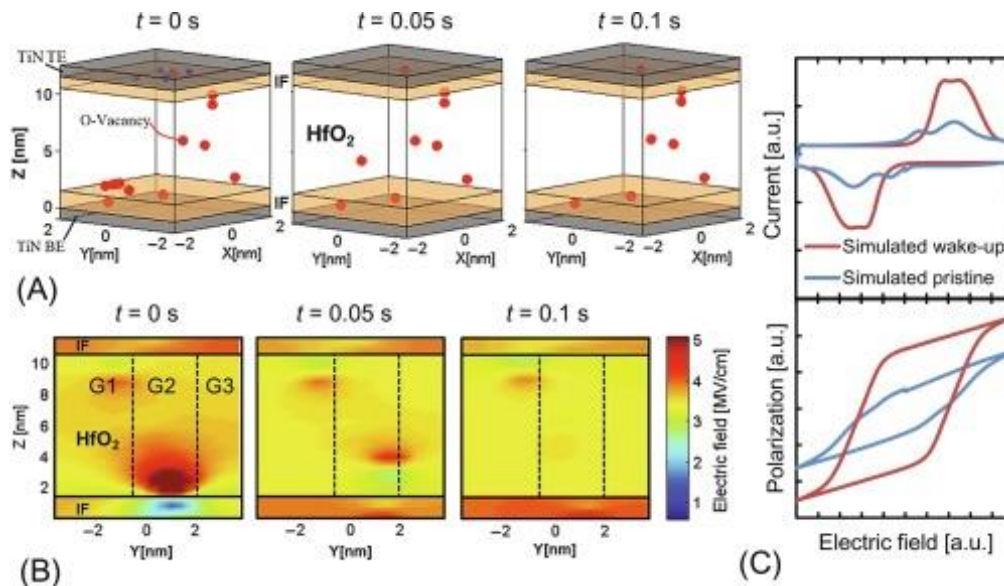
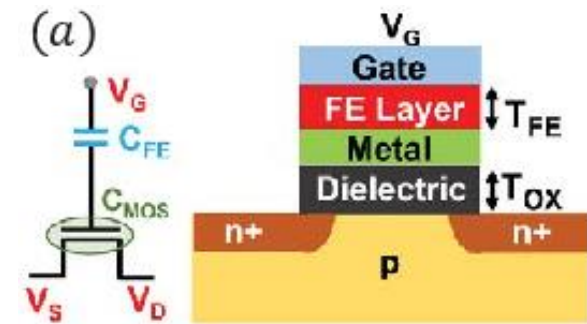


D. Zhao et al., Nat Commun 10, 2547 (2019)

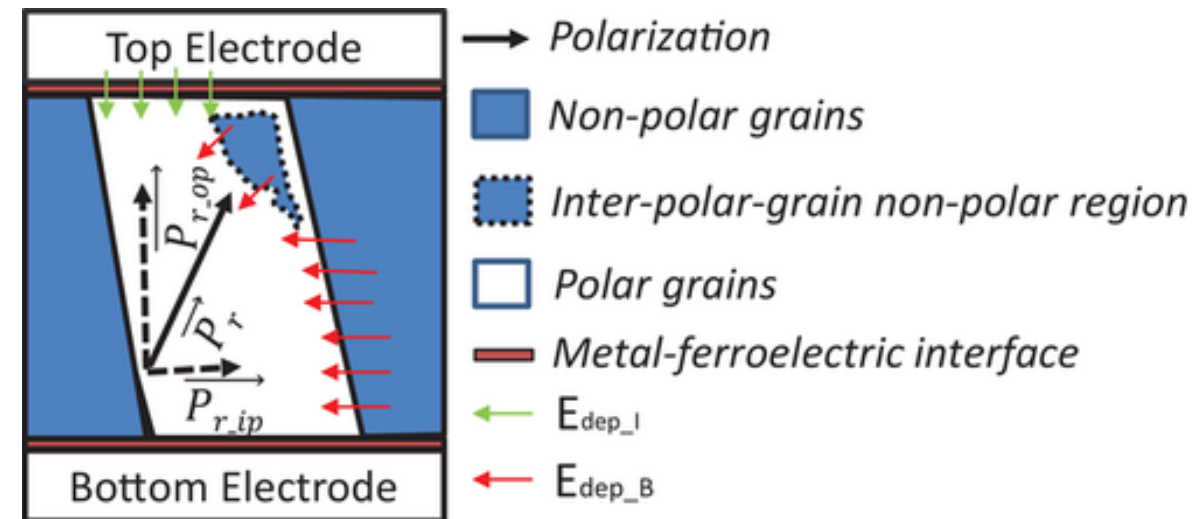


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- Measurements allow exploring depolarization dynamics (crucial for reliability)
- Possible causes of depolarization:
 - Series Capacitance (important in FeFETs)
 - Charge Screening Length / Dead Layers
 - Non-polar Grains
 - Defects



M. Pešić, L. Larcher, in «Ferroelectricity in Doped Hafnium Oxide: Materials, Properties and Devices» 2019, Woodhead Publishing



F. Mehmood et al., Adv. Mater. Interfaces 2019, 6, 1901180

SAWYER-TOWER CIRCUIT

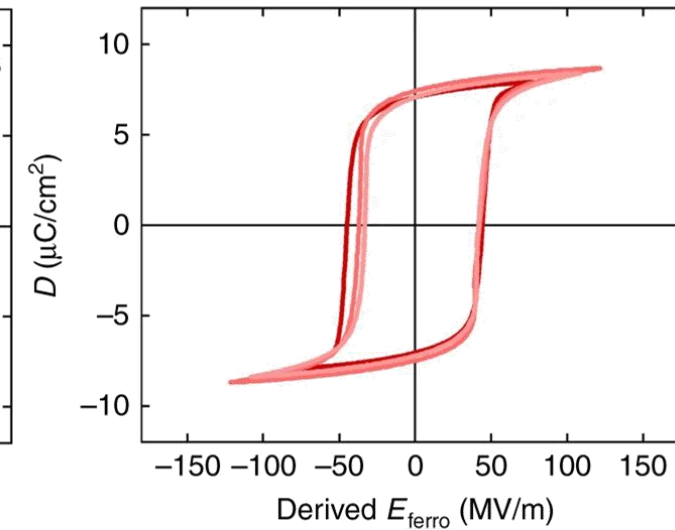
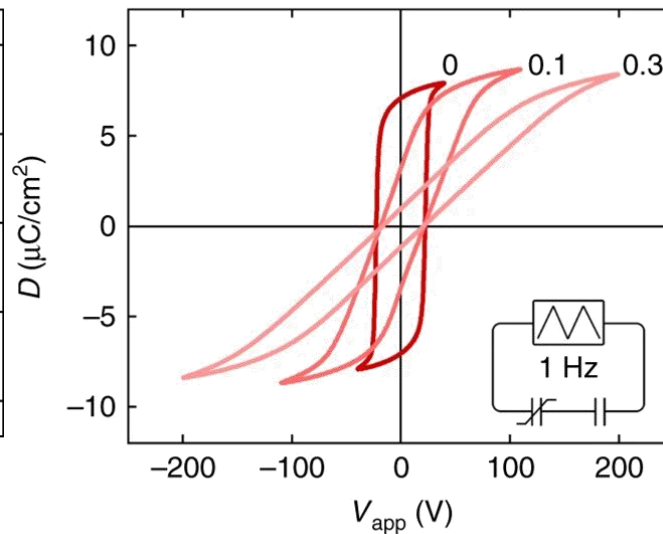
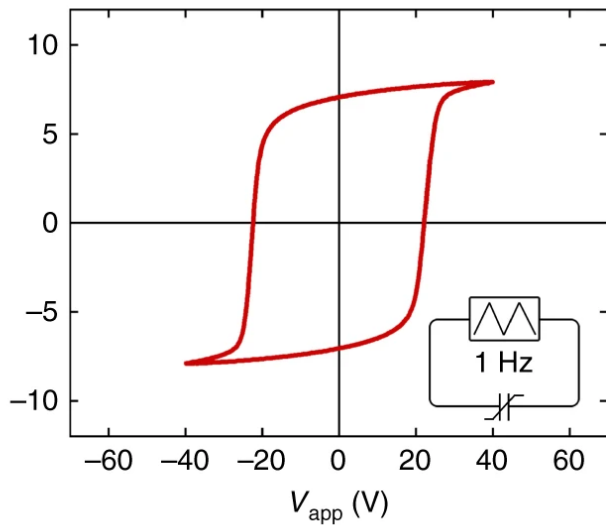
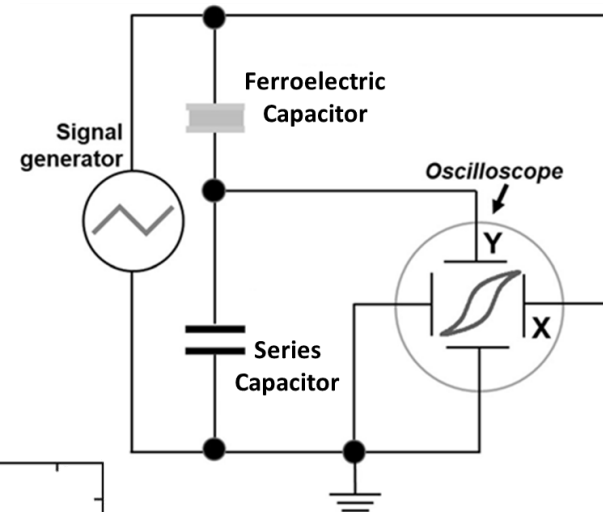
FIXIT

- **This circuit:**

- **Directly measures displacement and remnant polarization**
- **Relates depolarization field to suppressed remnant polarization**

$$V_{ser} @ (V_{app} = 0) = \frac{PA}{C_{ser} + C_{ferro}}$$

$$D = \frac{V_{ser} C_{ser}}{A}$$

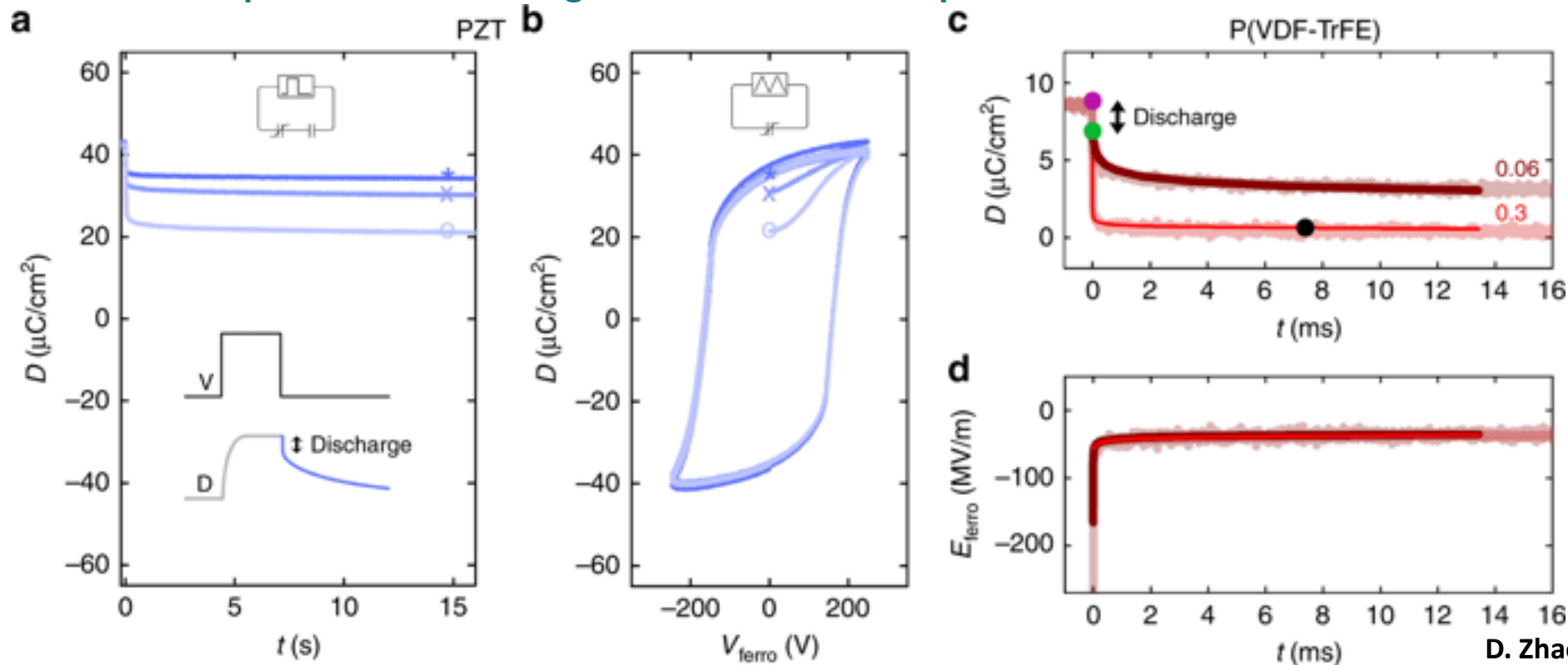


D. Zhao et al., Nat Commun 10, 2547 (2019)



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- Transient of depolarization dynamics using a Sawyer-Tower circuit
 - Sawyer-Tower arrangement to “tune” partial compensation and depolarization field
 - Integrating current over time to get displacement
 - Linear polarization discharge and Ferroelectric depolarization



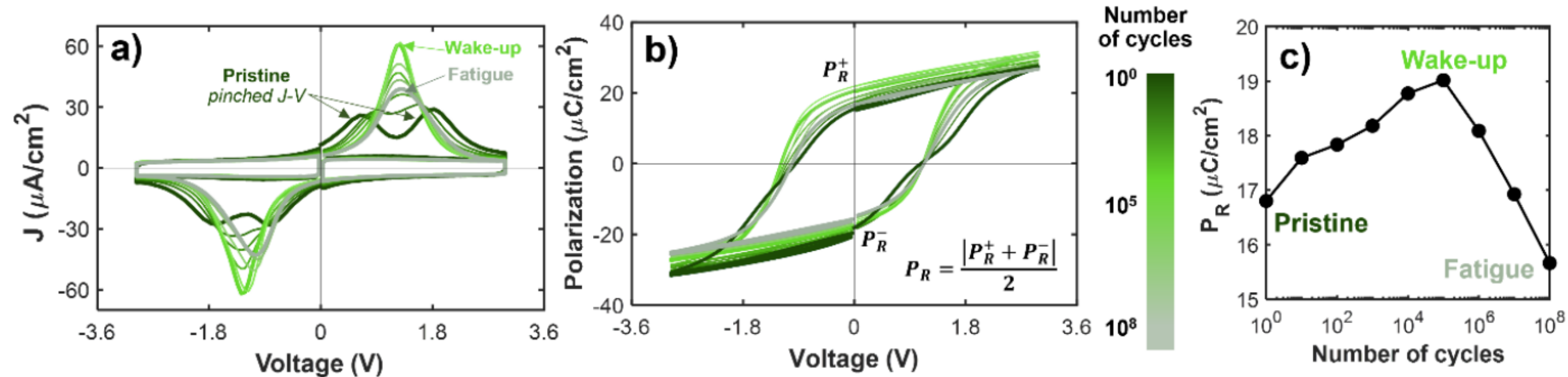
D. Zhao et al., Nat Commun 10, 2547 (2019)



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- Key device features change along the device lifetime
 - Initial J-V characteristic is “pinched” (low P_R : needs “wake-up” cycling, typically 10^3 to 10^4)
 - After wake-up, highest P_R and well-behaved J-V (single switching peak)
 - Further cycling lowers P_R and some domains do not switch anymore (fatigue)
 - Eventually, the device fails (endurance)



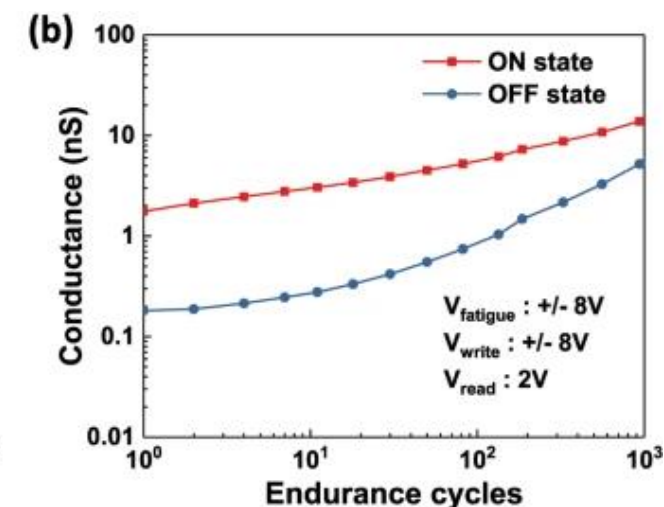
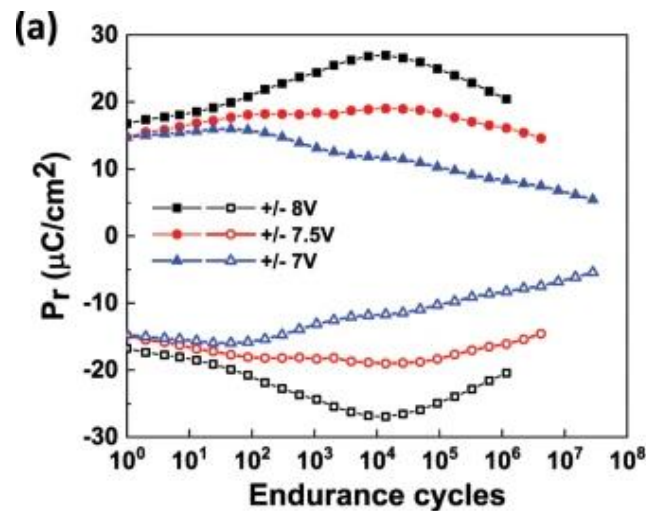
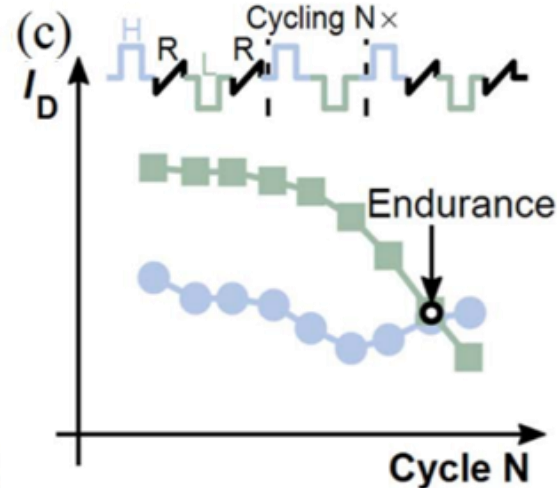
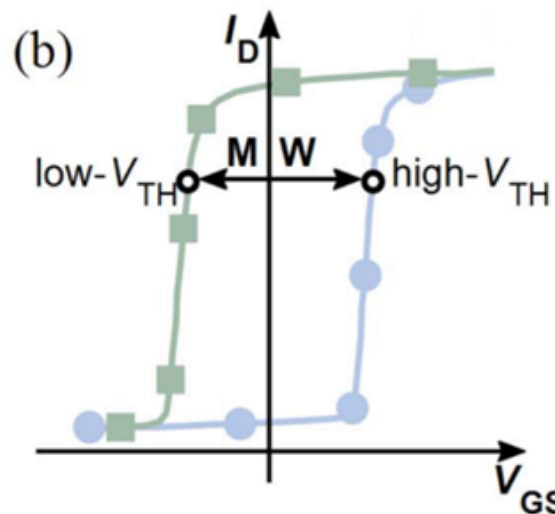
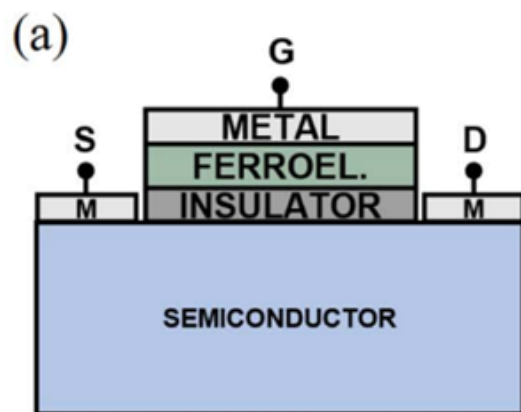
S. Vecchi et al., Adv Ele Mat, 2400204 (2024)

ENDURANCE AND AGING

FIXIT

- How many switching cycles can a ferroelectric device withstand?

- Depends on the device structure
 - FeFET/FTJ worse than FeRAM
- Depends on the applied bias/stress
- Thought to be limited by
 - IL/DE degradation
 - Phase changes and domain pinning
 - Defects generation in the stack (breakdown)



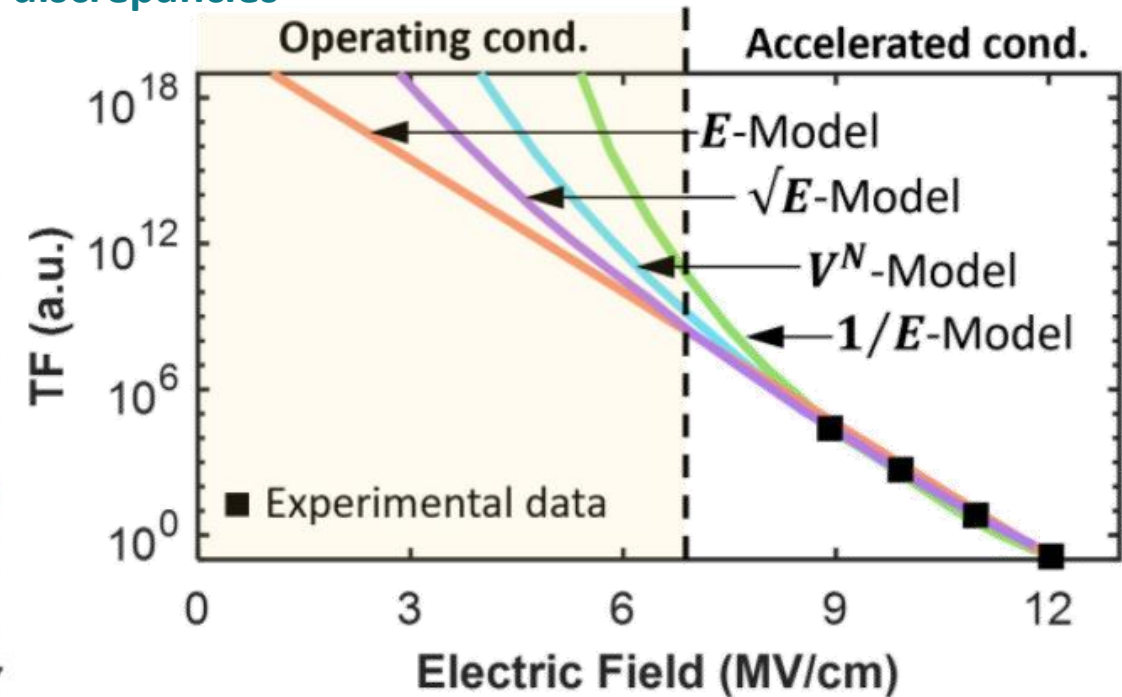
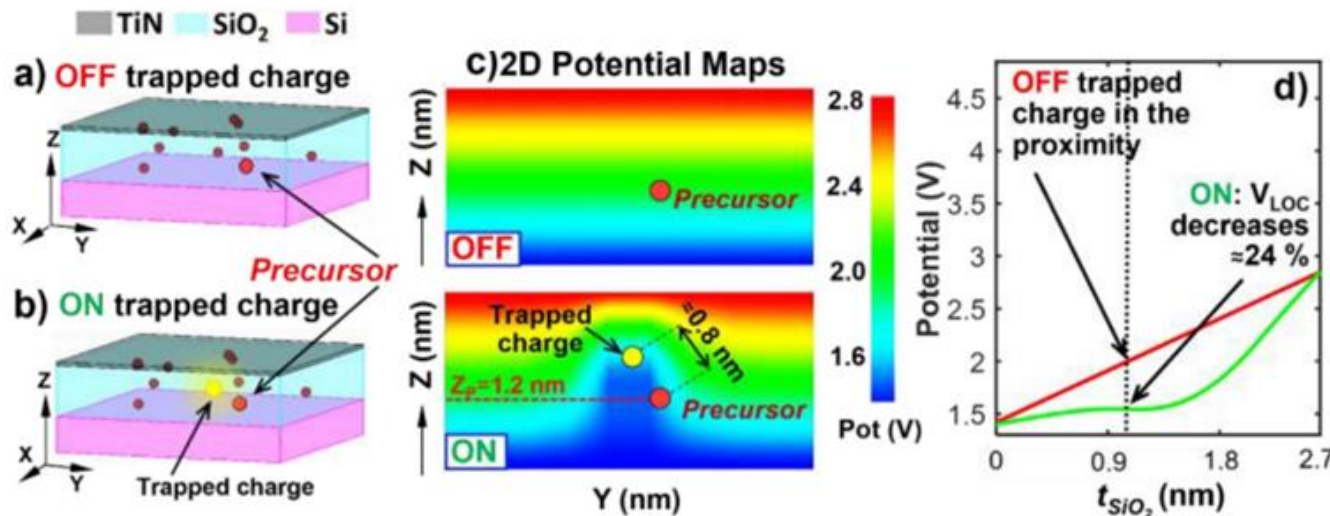
H. Ryu et al., Sci Rep, 9 20383 (2019)

N. Zagni et al., Proc. of IEEE, 111 2 (2023)



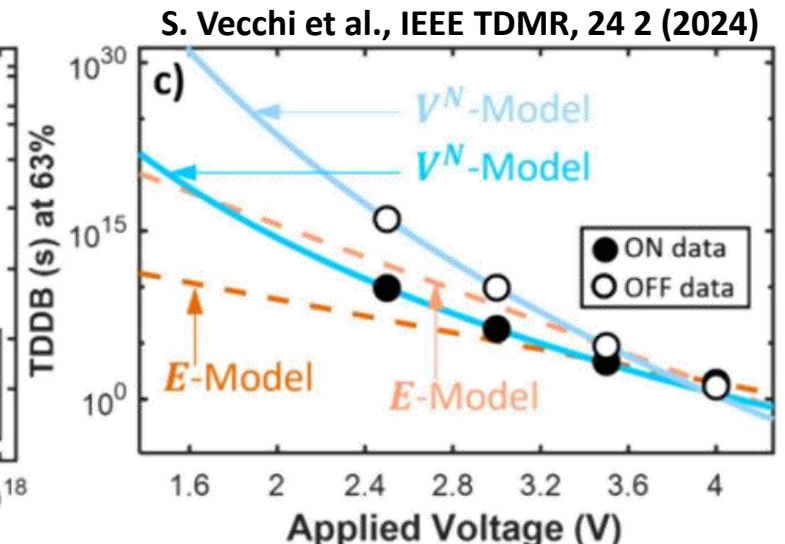
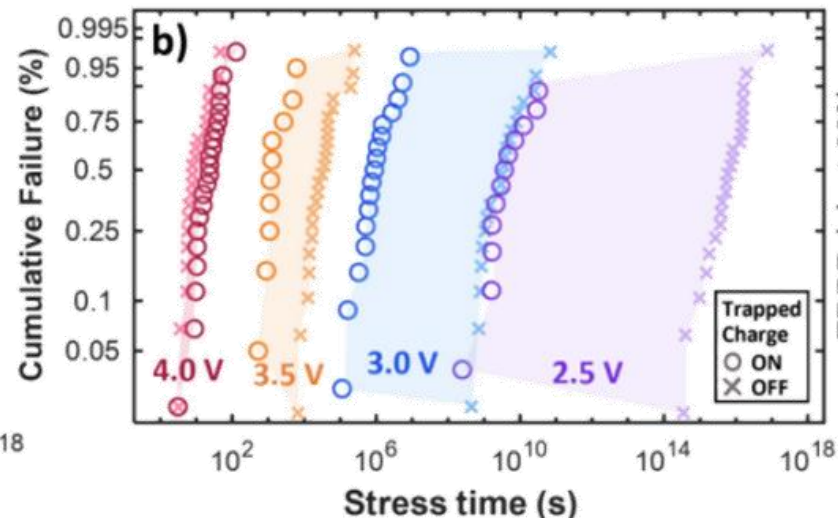
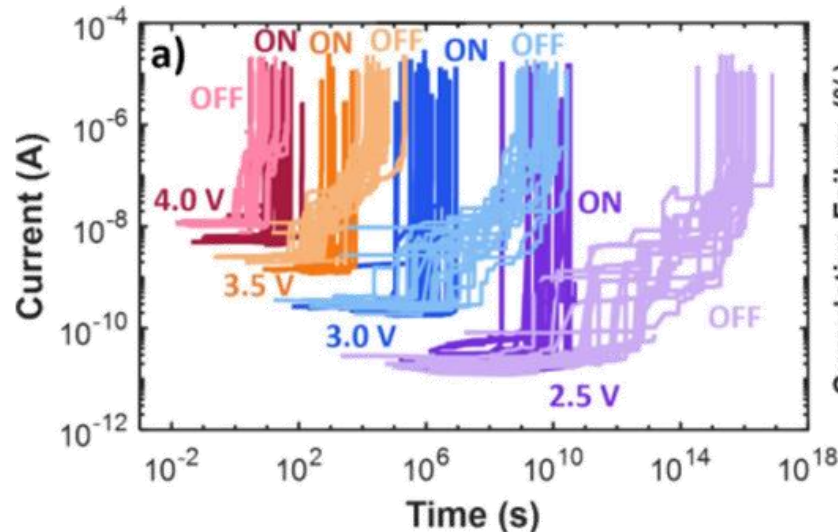
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- Electric and temperature fields in the stack promote defect generation, eventually leading to breakdown
 - Many models in the literature: all agree on predicting device lifetime at high fields
 - All agree on predicting device lifetime at high fields
 - Strongly diverge when projecting at operating conditions
 - Recently introduced carrier injection model reconciles such discrepancies
 - Highlights the role of carrier trapping into defect precursors
 - Trapping in precursors facilitates defects generation
 - Trapping strongly affects internal electric field!!



S. Vecchi et al., IEEE TDMR, 24 2 (2024)

- Electric and temperature fields in the stack promote defect generation, eventually leading to breakdown
 - Features of BD as related to trapping are strongly material-dependent
 - In HfO_2 it has been suggested that trapping at O vacancies (that may exist in 5 charge states, -2 through +2) accelerate BD!
 - In SiO_2 the same mechanism leads to a delay in BD dynamics!
 - What about in ferroelectric HfO_2 ? And in other material systems of interest (e.g., AlScN)?
 - Internal field in ferroelectrics further complicated by 3D grain-dependent polarization
 - Effect of trapped charge superposed to that of polarization (highly complex interactions between trapping and polarization)
 - Hard to predict how BD dynamics takes place in ferroelectrics



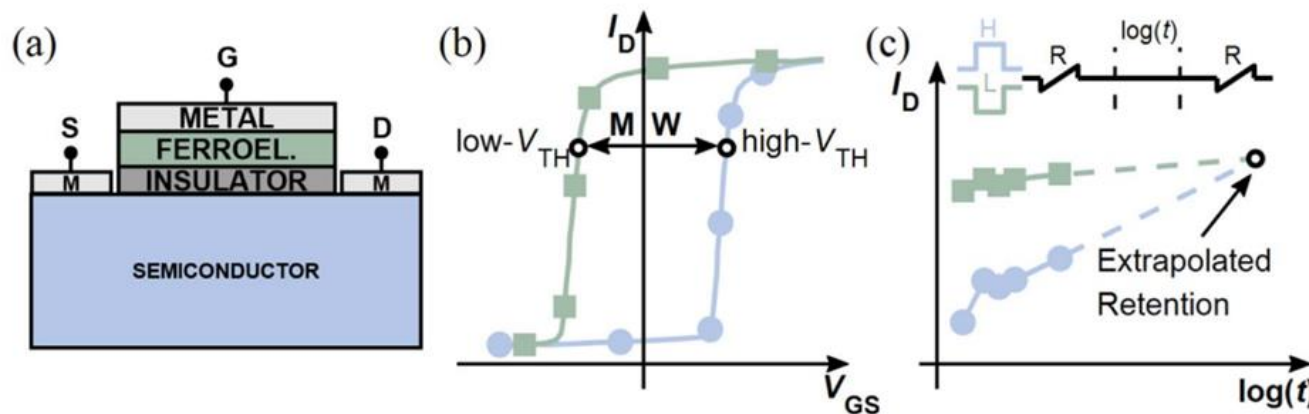
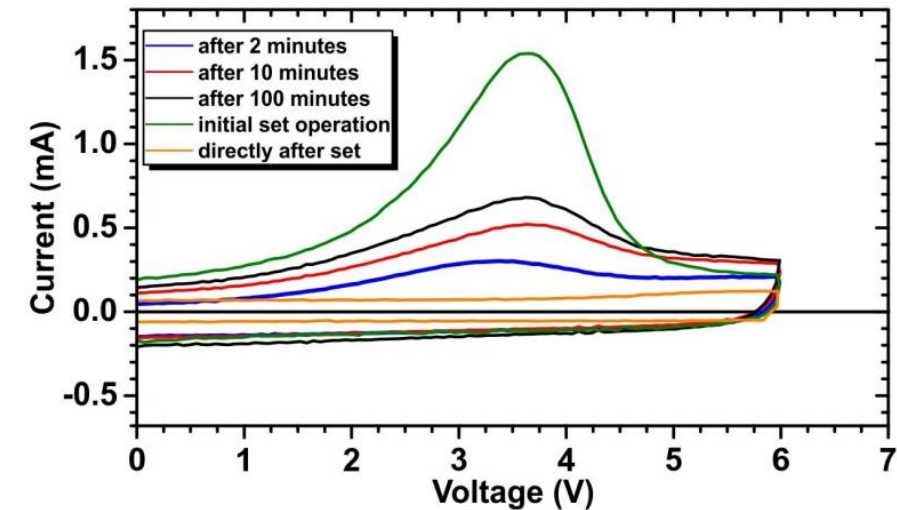
S. Vecchi et al., IEEE TDMR, 24 2 (2024)

POLARIZATION STATE RETENTION

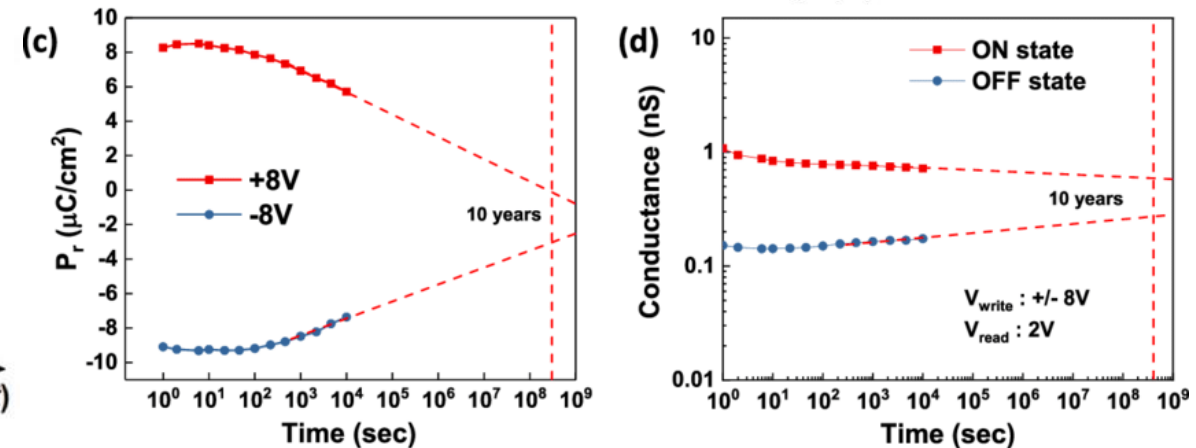
FIXIT

- How long can we keep information stored in a ferroelectric device?
 - Depends on the device structure
 - FeFET/FTJ worse than FeRAM
 - Depends on the polarization state (implications for multi-level storage)
 - Thought to be limited by
 - Depolarization field (in general)
 - Complex internal field distribution
 - Defects and associated trapped charge
 - Possible domain-domain interactions

B. Max et al., IEEE IMW (2019)



N. Zagni et al., Proc. of IEEE, 111 2 (2023)



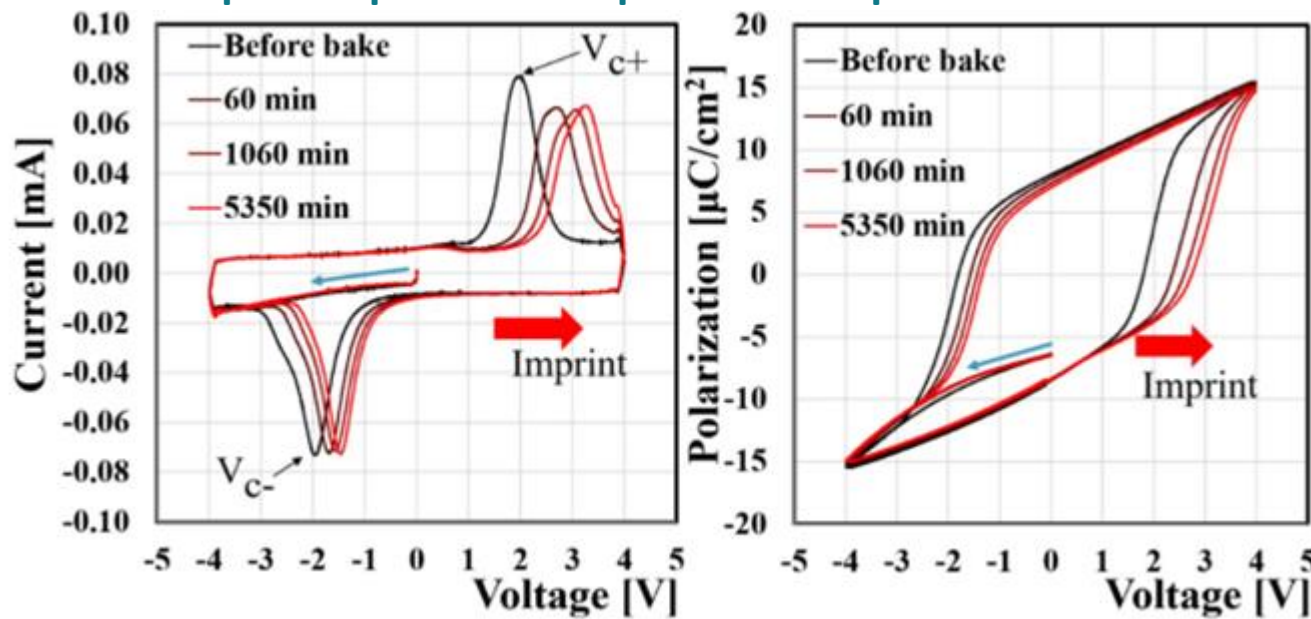
H. Ryu et al., Sci Rep, 9 20383 (2019)



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- **Unique reliability feature of ferroelectrics**

- **“Horizontal” shift of I-V and P-V curves with cycling: Ferroelectric develops a preferential polarization state!**
 - One polarization state becomes preferred over the other, which induces asymmetric retention loss at 0V
 - Changes the voltage required for (complete/partial) switching: critical for neuromorphic and in-memory computing!
- **Coercive voltage shift toward either more positive or more negative values depending on the polarization**
 - If in the $-P_s$ ($+P_s$) state, $+E_c$ ($-E_c$) will increase (decrease)
- **Imprint reported to depend on temperature and device baking**



N. Zagni et al., Proc. of IEEE, 111 2 (2023)

Phenomenon attributed to the electrostatic effect of electron trapping and de-trapping at defects and their redistribution across the device and at the FE/DE interface.

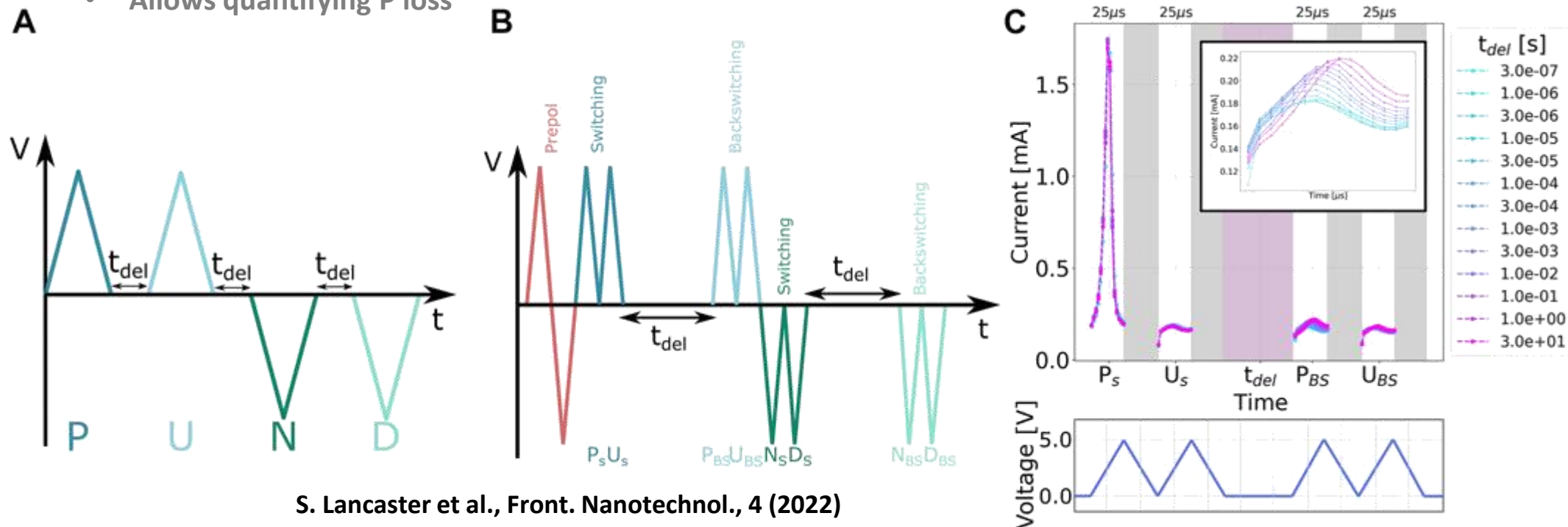
Two different imprint phenomena identified:

- **Time-dependent: shift of the P-V loop over time**
- **Fluid: a more dynamic effect that strongly depends on the characteristics of the switching pulse applied**

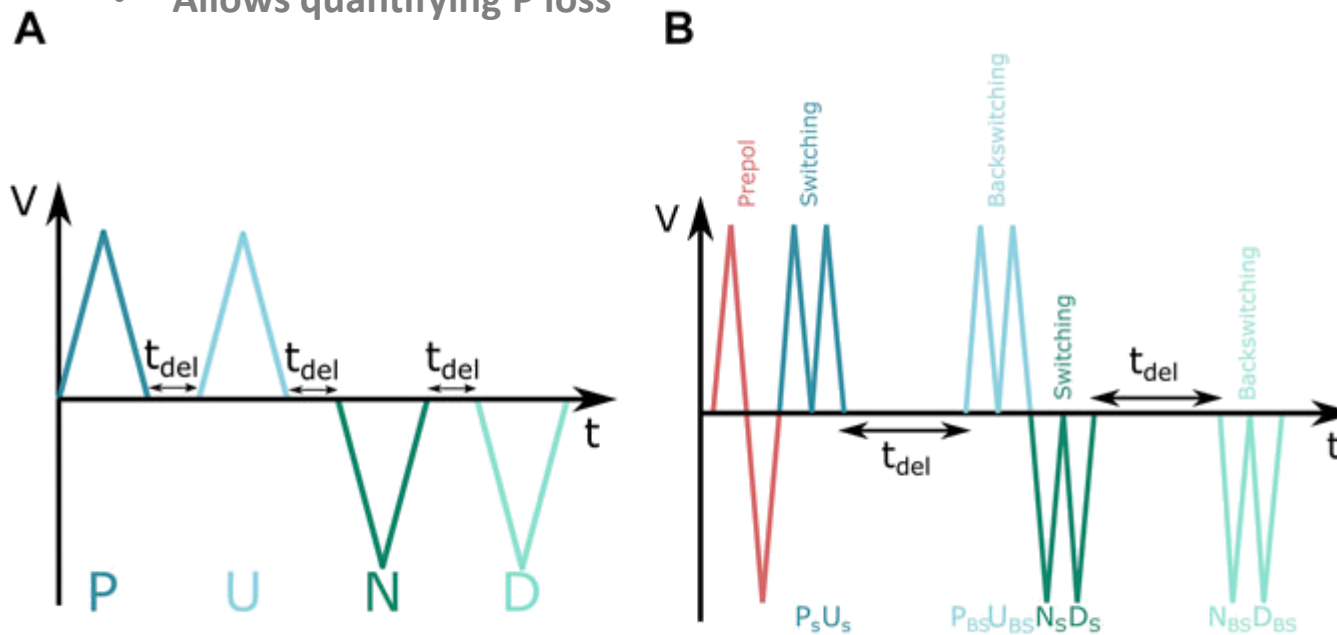
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- Ferroelectric devices tend to lose their polarization
 - Competing effects of the depolarization field, internal bias field and charge trapping
 - Measurements done by extending the PUND concept introducing some delay in between pulses
 - Increasing delay results in more current detected in the back-switching pulses (both polarities)
 - Some domains flipped in the meantime
 - Allows quantifying P loss



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S. Lancaster et al., Front. Nanotechnol., 4 (2022)

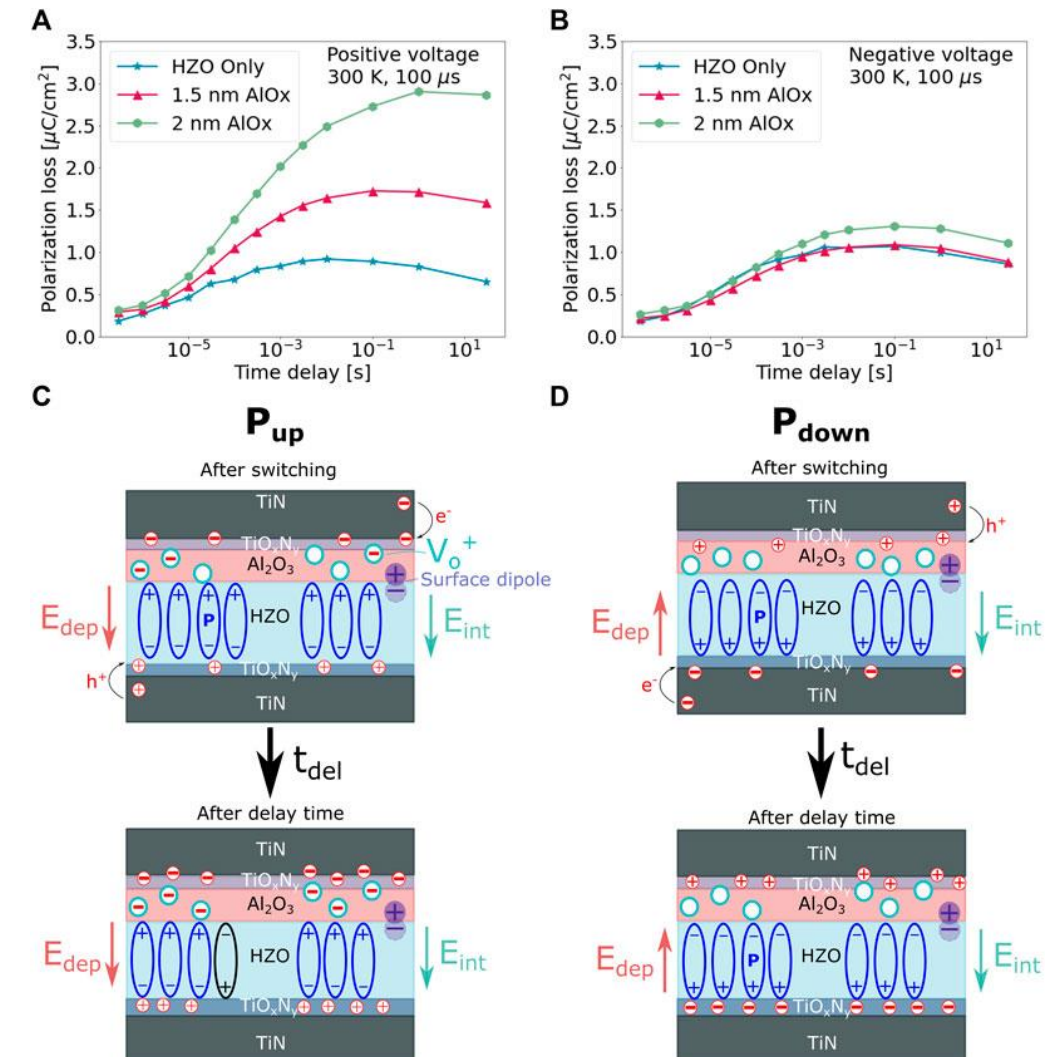
$$P_{loss} = \int_0^{t_{pls}/2} (P_{BS} - U_{BS}) dt$$

$$\widetilde{P}_{loss} = \frac{\int_0^{t_{pls}/2} (P_{BS} - U_{BS}) dt}{\int_0^{t_{pls}/2} (P_S - U_S) dt}$$

RETENTION AND BACKSWITCHING

FIXIT

- **Ferroelectric devices tend to lose their polarization**
 - **Polarization loss is asymmetric and depends on DE**
 - Thicker DE implies less charge injection and larger E_{DEP}
 - Different oxygen density in the two layers (DE and FE) may induce surface dipoles, while oxygen motion counteracts this surface dipoles field
 - **Asymmetric structure means asymmetric charge injection**
 - Facilitates P loss in one state more than in the other
 - **Short-term retention losses seem to saturate at 10s**



S. Lancaster et al., Front. Nanotechnol., 4 (2022)

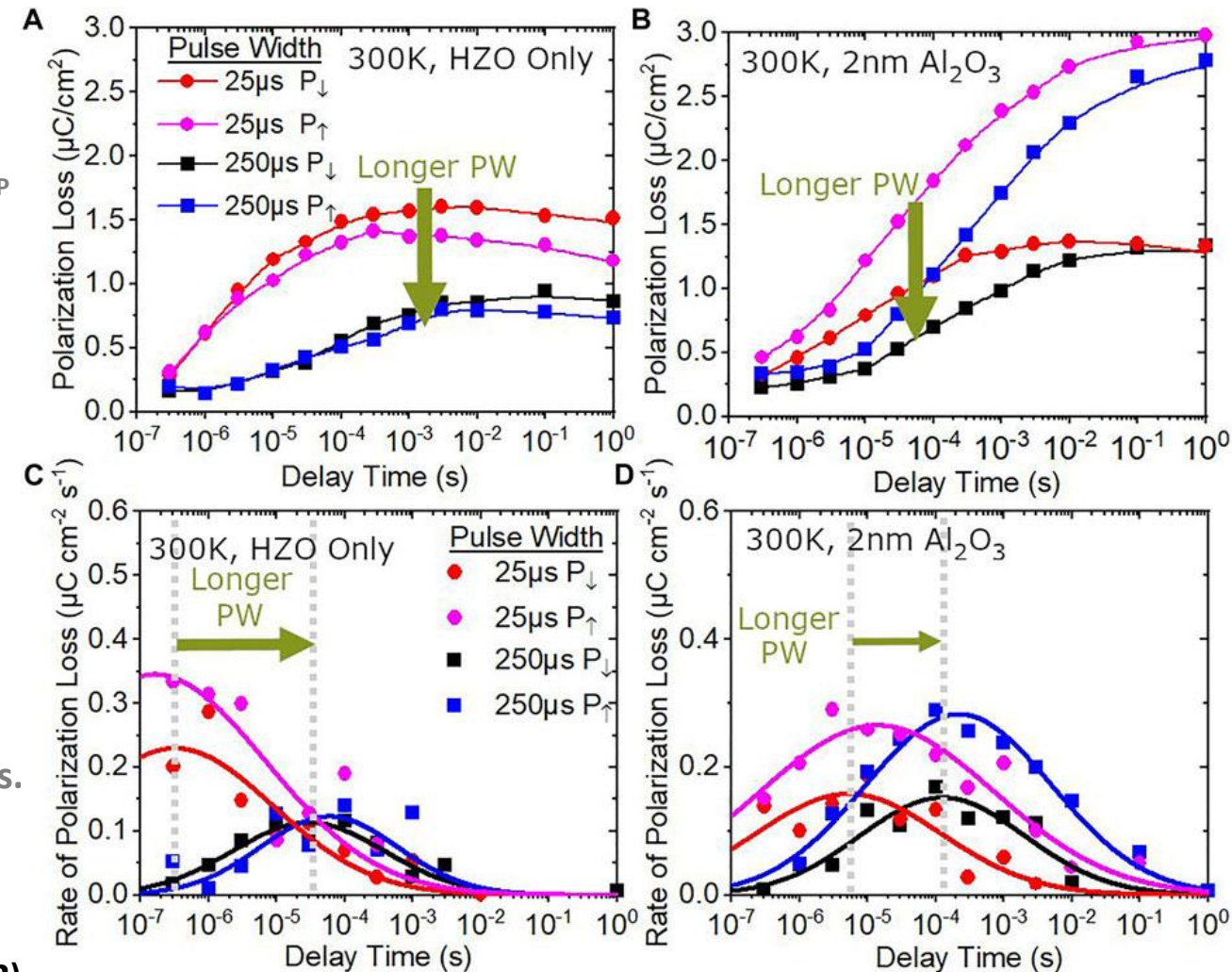


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 - **Dependent also on pulse width**
 - Longer pulse widths decrease the rate of P loss and shift the polarization loss to longer times
 - This shift is consistent with a lower E_{DEP} due to enhanced screening caused by injected charge carriers.



S. Lancaster et al., Front. Nanotechnol., 4 (2022)

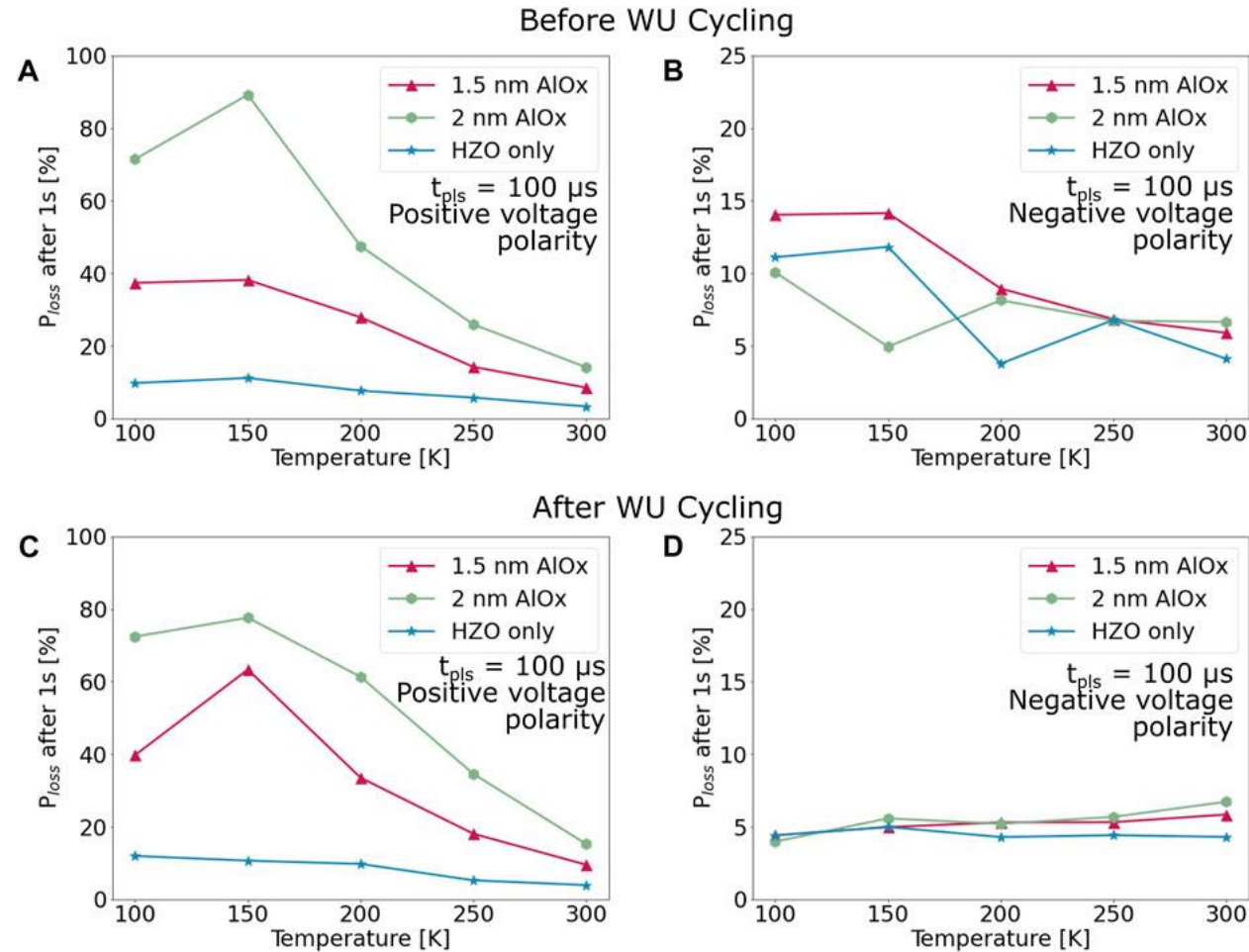


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 - **Dependent also on temperature**
 - Lower T slows down charge injection giving less screening and more P loss

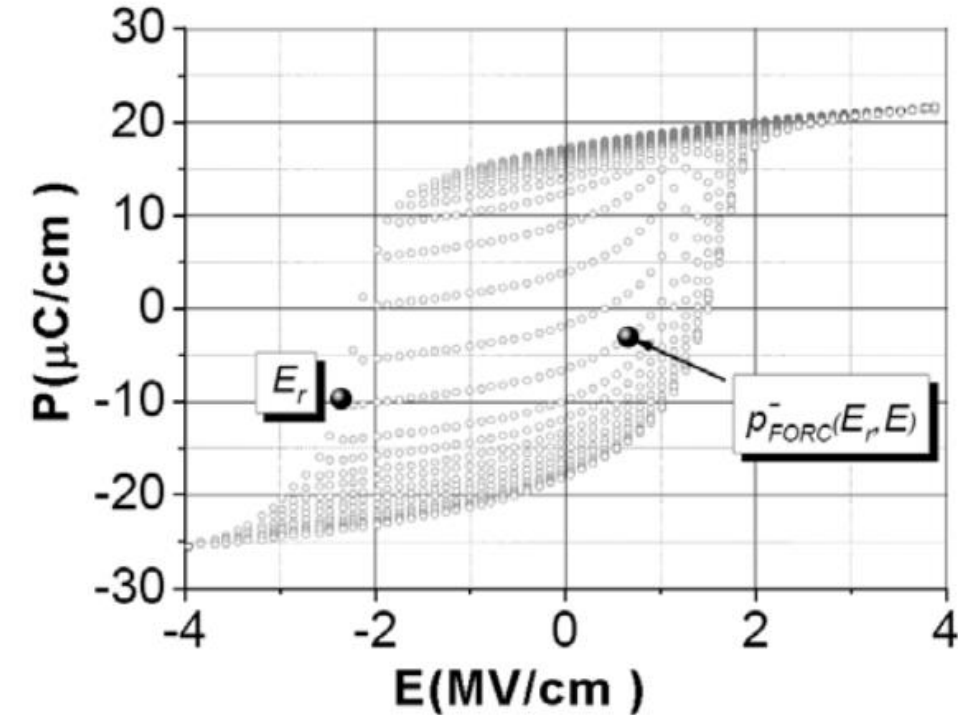


S. Lancaster et al., Front. Nanotechnol., 4 (2022)



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- Imprint is typically assessed by:
 - Conventional P-V curves (measure the coercive voltage shift)
 - First-Order Reversal Curves (FORC)
 - Taken from magnetic materials characterization
 - Provide insight into the relative proportions of reversible and irreversible components of polarization
- Measurements of minor hysteresis loops between E_{SAT} and a variable reversal field $E_R \in (-E_{SAT}, E_{SAT})$:
 - i) saturation under a positive field $E \geq E_{SAT}$
 - ii) ramping down to the reversal value E_R
 - iii) increasing the field back to the positive saturation, with p_{FORC} a function of the actual and reversal field
 - iv) calculate the parameter ρ
- The FORC diagram is a contour plot of the FORC distribution, defined as the mixed second derivative of polarization p_{FORC} with respect to E_R and E

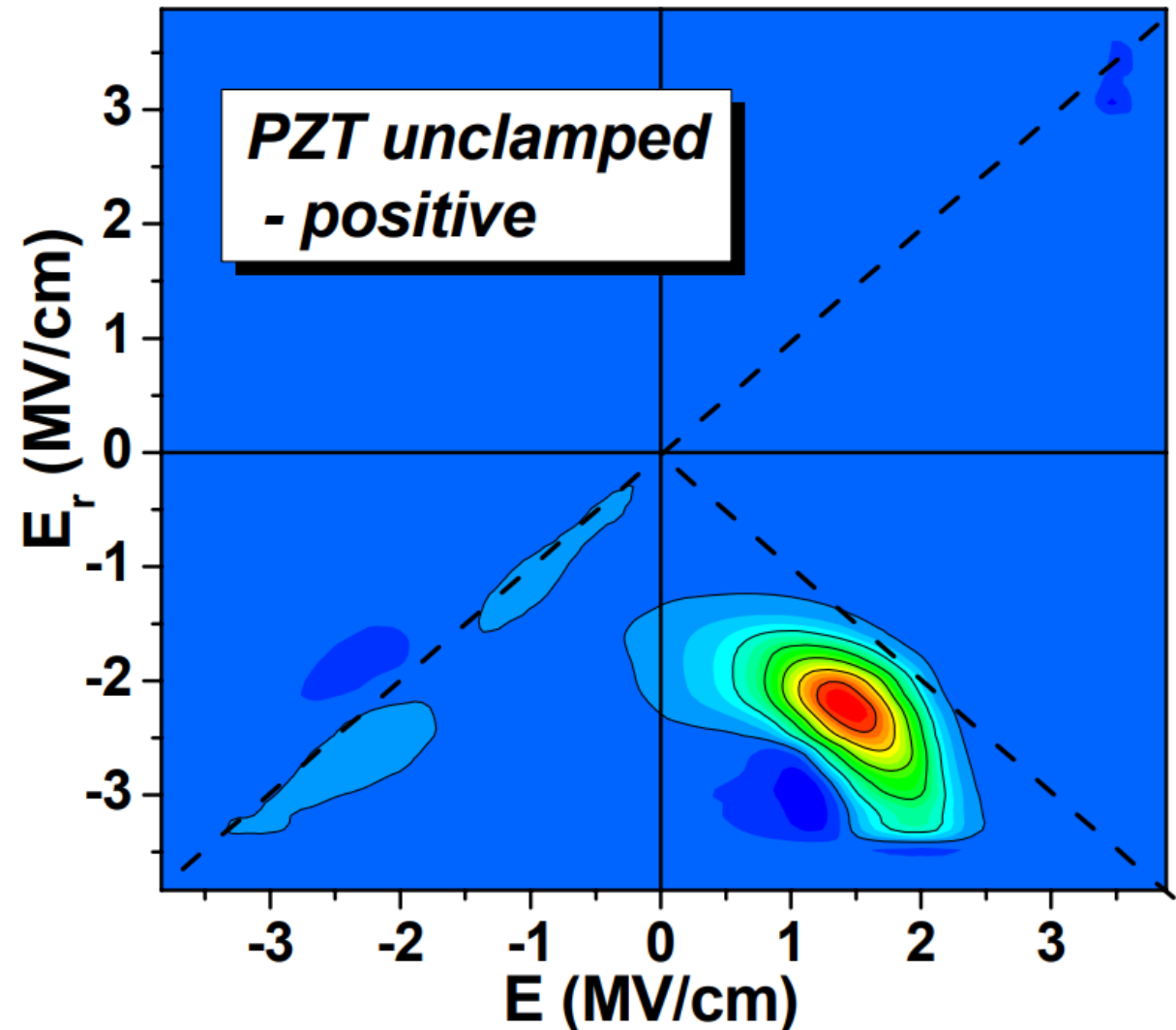


$$\rho^-(E_r, E) = \frac{1}{2} \frac{\partial^2 p_{FORC}^-(E_r, E)}{\partial E \partial E}$$

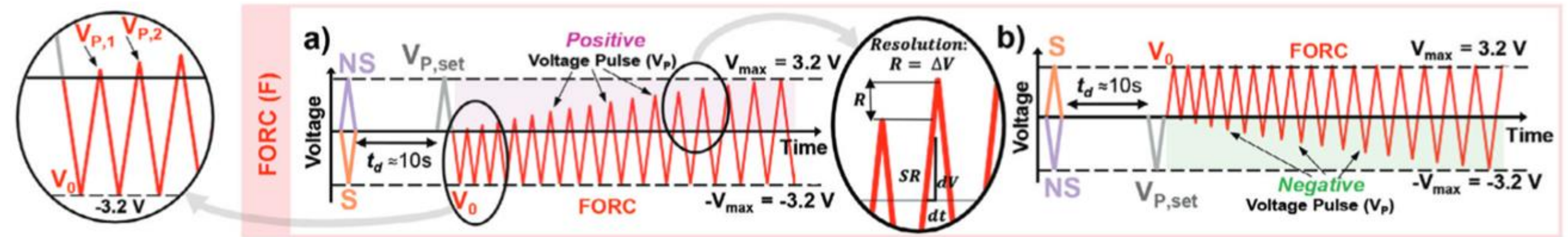
L. Mitoseriu, Processing and Application of Ceramics, 3, 1-2 (2009)



- **FORC plot**
 - The 3D-distribution $\rho(E_r, E)$ describes the sensitivity of polarization with respect to the reversal and actual electric field
 - Can be used to evaluate imprint by looking at the polarization spot position with respect to the main diagonal and off-diagonal axes
 - Can be used to get insights into reversible (along the main diagonal) and irreversible (along the off diagonal) components of switching



- Advanced FORC-based methodologies to evaluate time-dependent and fluid imprint together
 - First-Order Reversal Curves (FORC)
 - Unipolar Reversal Curves (URC)
 - Delayed URC (D-URC)
- Time-dependent Imprint
 - Domains switched in one P harder to switch in the opposite P with increasing delay time
- Fluid Imprint
 - Upon partial switching into a given P state, the film develops a gradual preference for that P state

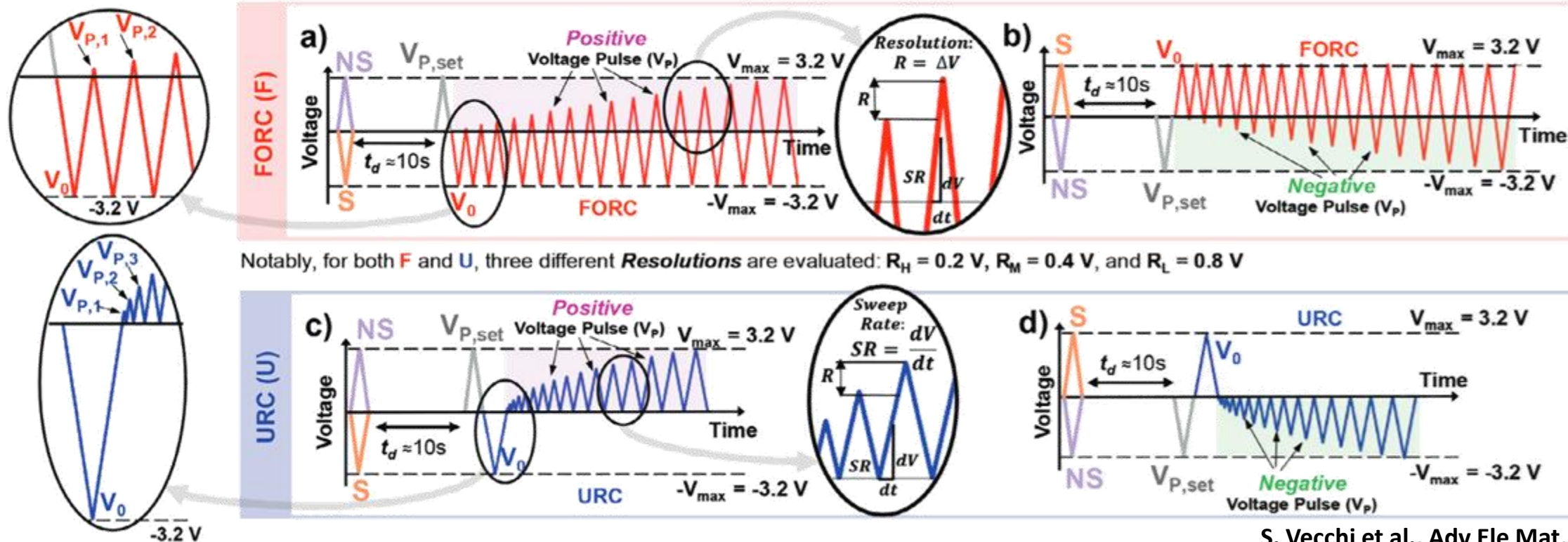


IMPRINT AND FORC/URC/D-URC

FIXIT

- **FORC and URC**

- We use a FORC waveform (modified to include pre-poling and pre-conditioning)
- We also use a novel URC waveform (also with pre-poling and pre-conditioning)
- For each pulse we can integrate the switched polarization above the time axis and compare FORC vs. URC



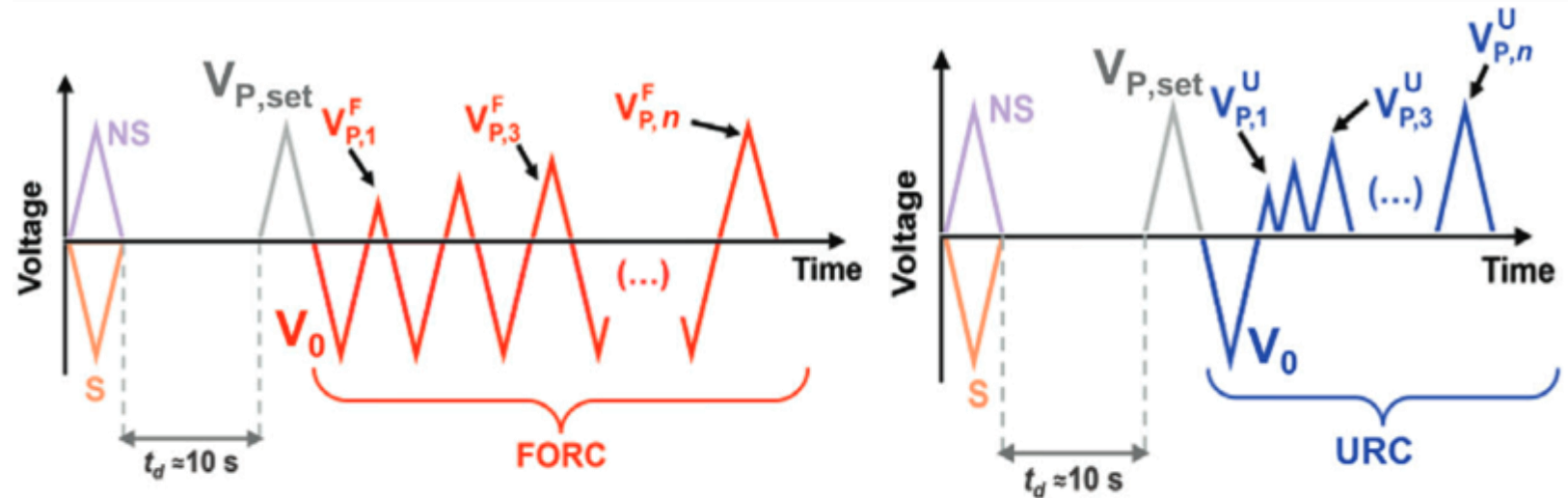
S. Vecchi et al., Adv Ele Mat, 2400204 (2024)



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- By defining appropriate switched polarization indicators for FORC and URC we can assume that

If no imprint occurs, then the EFFECTIVE FORC switched P must equal the URC switched P for each pulse



a) $\forall V_{P,i} \quad i = 2, \dots, n$ ($n = \text{number of } V_P \text{ for each } R$):

$$\begin{array}{ccc} \text{FORC:} & & \text{URC:} \\ P_{EFF,i}^F(V_{P,i}) = P^F(V_{P,i}) - P^F(V_{P,i-1}) & \xleftrightarrow{\text{Comparison}} & P^U(V_{P,i}) \end{array}$$

Here the polarization associated to the previous V_P is subtracted to compare the quantity of switched domains between **FORC** and **URC**

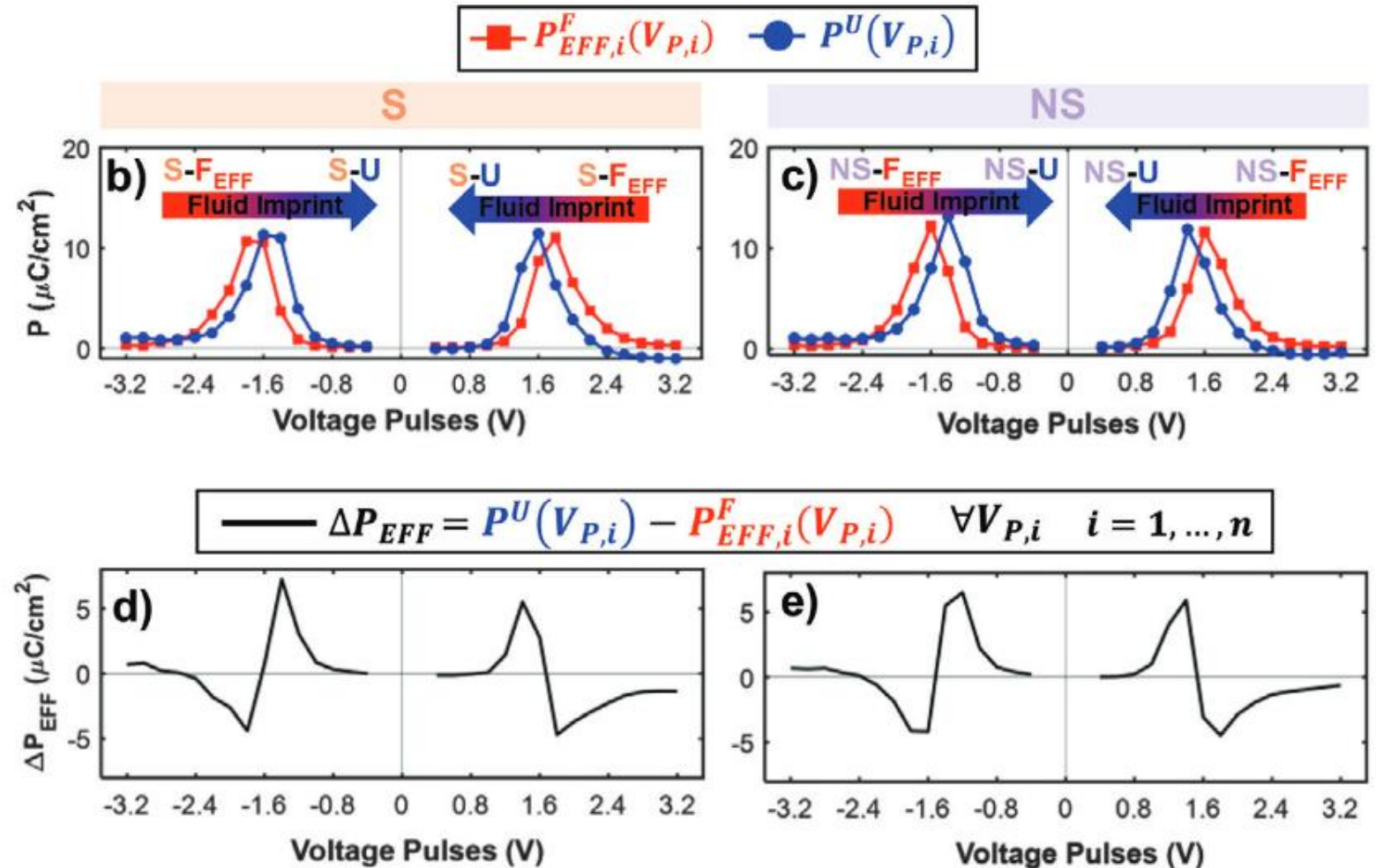
Notably, for $V_{P,1}$: $P_{EFF,1}^F(V_{P,1}) = P^F(V_{P,1}) = P^U(V_{P,1})$

S. Vecchi et al., Adv Ele Mat, 2400204 (2024)

- Easy to see that imprint occurs

The two curves are not the same and the URC curve anticipates the EFFECTIVE FORC regardless of polarity and pre-conditioning pulse properties

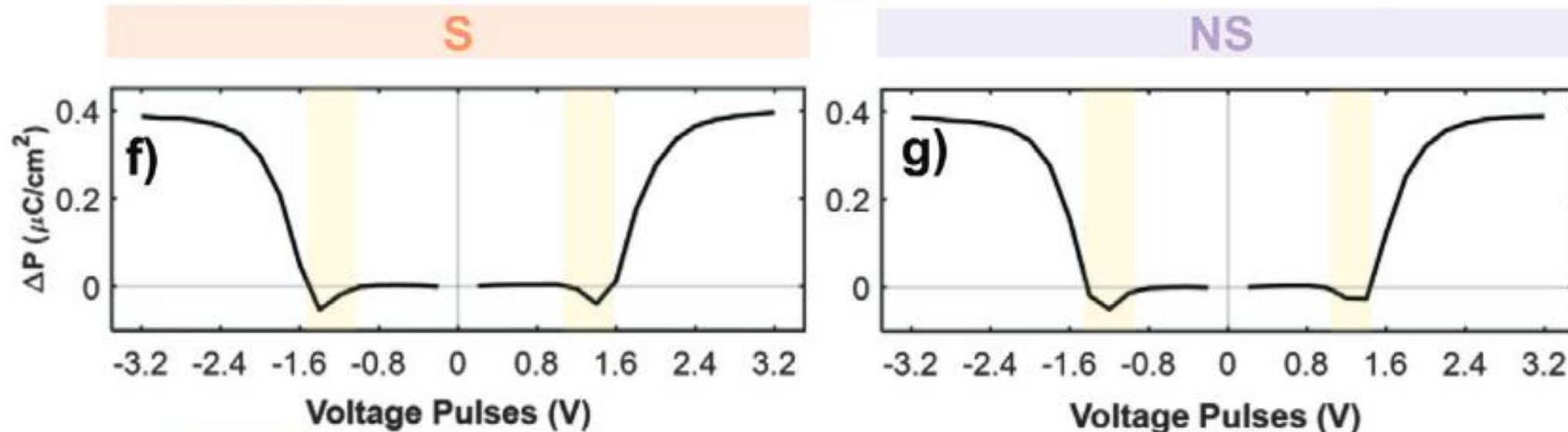
- Manifestation of FLUID IMPRINT



- Direct comparison of FORC (not EFFECTIVE FORC) and URC reveals that fluid imprint can be quite strong!

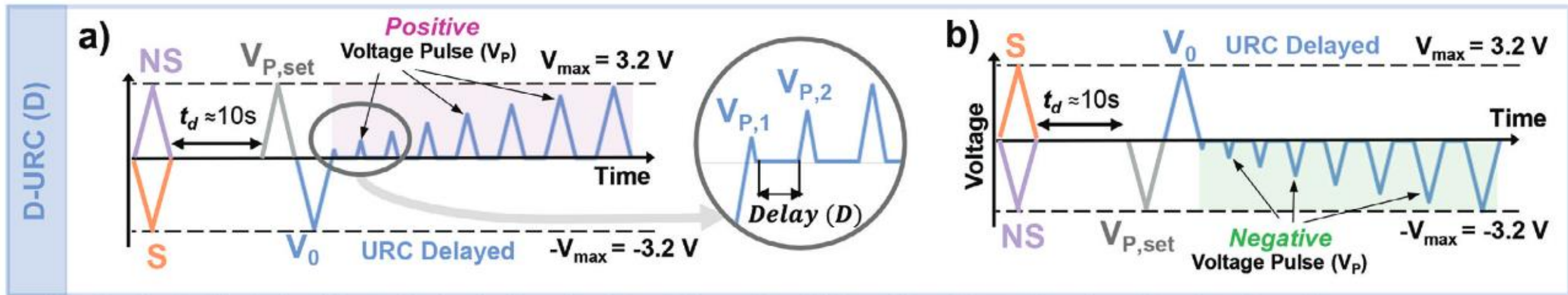
$$\text{---} \Delta P = P^F(V_{P,j}) - P^U(V_{P,j})$$

$$\forall V_{P,j} \quad j = 1, \dots, n \quad (n = \text{number of } V_P \text{ for each } R)$$



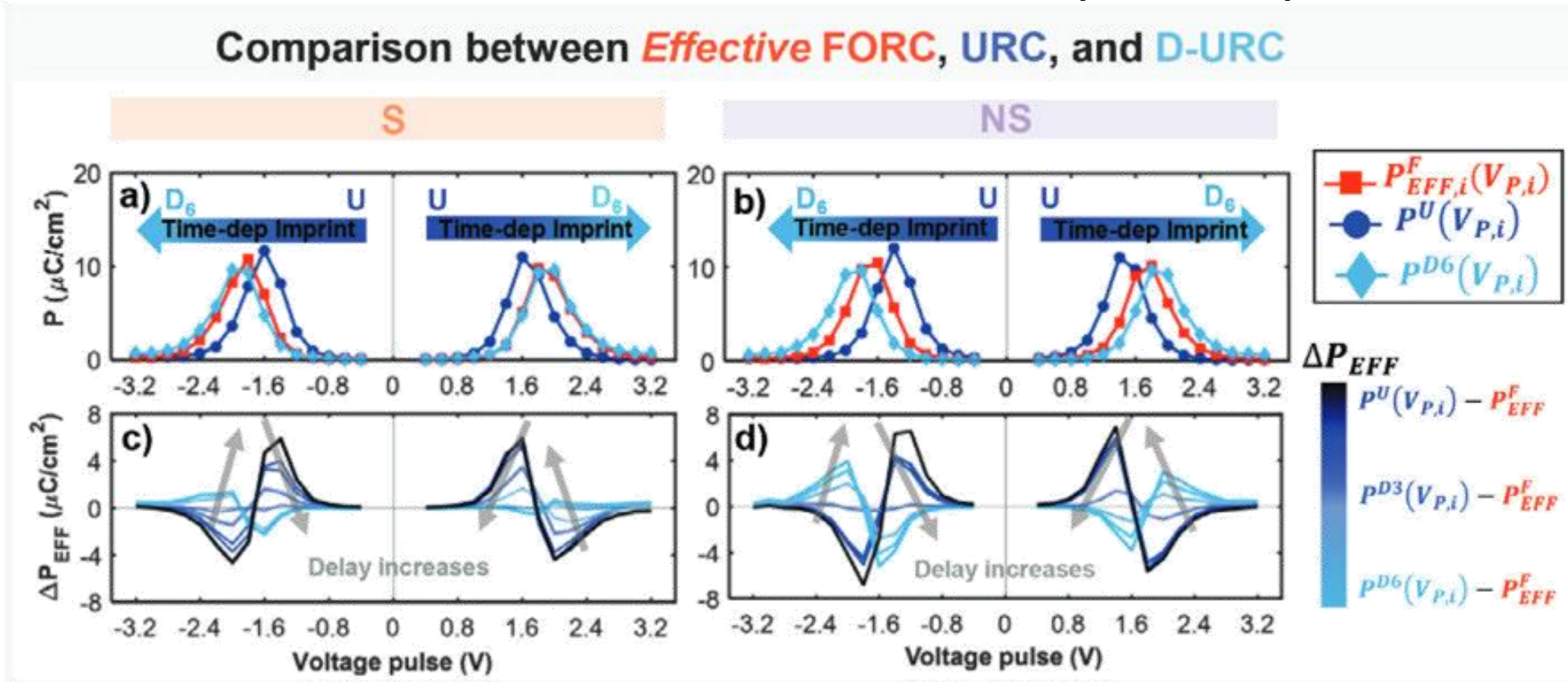
Close to the voltage at which most of the domains switch when assisted by the fluid imprint $\rightarrow$ **URC** switching > **FORC** switching!

- Time-dependent imprint can be evaluated using Delayed-URC (D-URC)
- Similar to URC, but a delay is inserted in between pulses
- Delay is constant but can be varied (here from 100 μ s to 10s)

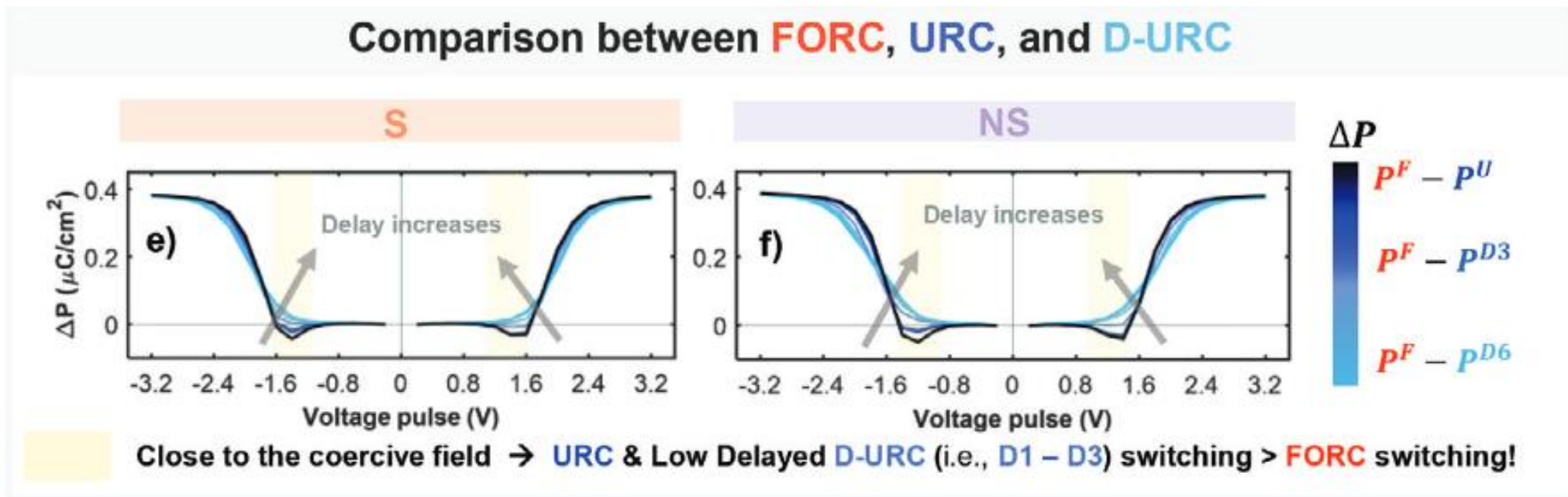


Notably, for **D**, Six **Delay Times**: $D_i, i = 1 \dots 6 \rightarrow D_1 = 100 \mu s, D_2 = 500 \mu s, D_3 = 50 ms, D_4 = 1 s, D_5 = 5 s, D_6 = 10 s$

- Results suggests that un-switched domains gradually develop a preference for their actual polarization state over time, which is another manifestation of time-dependent imprint.

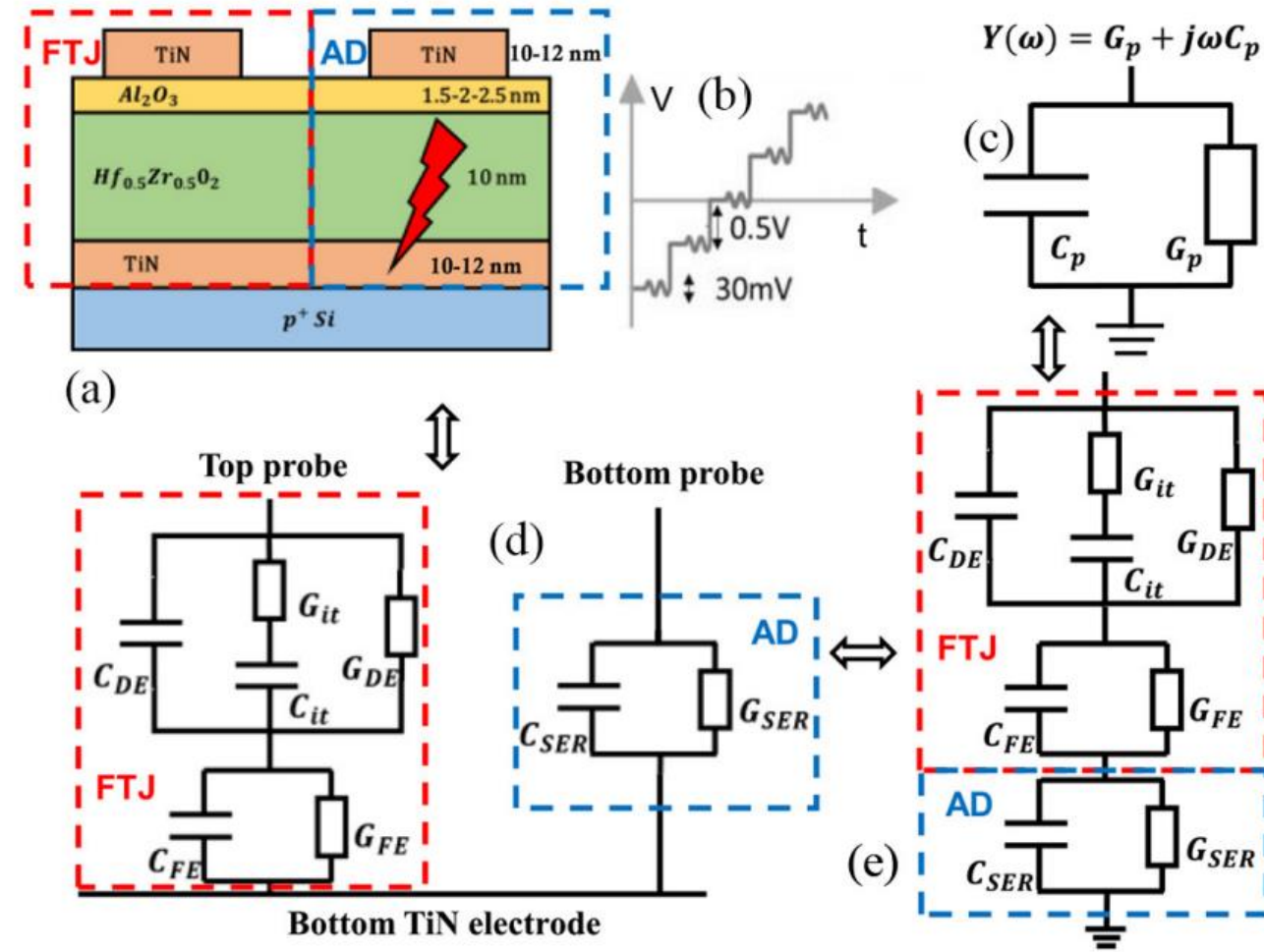


- **Direct comparison of FORC (not EFFECTIVE FORC) URC and D-URC confirms the time-dependent imprint!**
- **If the delay is short (less than approximately 1s) the advantage of partial switching is still present when one wants to further switch domains in the same direction**
- **If the delays is long enough (longer than approximately 1s) then the time-dependent imprint effect becomes dominant**



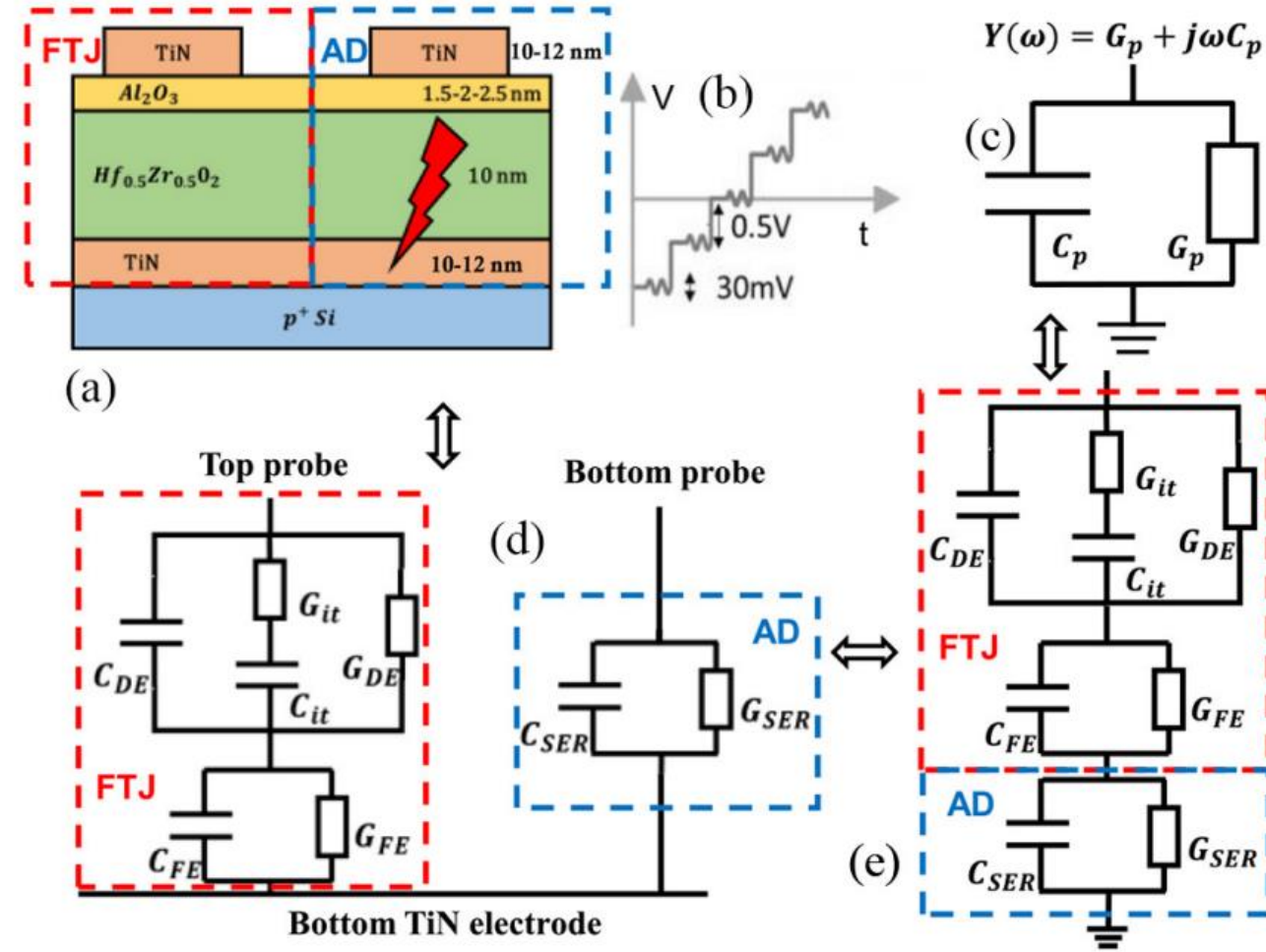
S. Vecchi et al., Adv Ele Mat, 2400204 (2024)

- Based on impedance measurements at different voltages and frequencies (multi-voltage C-f/G-f)
 - Can reveal many different interesting quantities involved in device operation and reliability
 - Ferroelectric (and dielectric) permittivity
 - Conductance of the different layers (leakage and associated defects)
 - Parasitic contributions (access impedance)
 - 1st-order approximation of interface defects and/or dead/interface layers
- Classical AC impedance measurements at:
 - Different DC bias (thus different polarization)
 - Different AC frequencies
- Needs an appropriate small-signal device model
 - Must include salient features of the device stack
 - Needs to consider access (series) impedance



L. Benatti et al., IEEE TDMR, 22 3 (2022)

- Based on impedance measurements at different voltages and frequencies (multi-voltage C-f/G-f)
 - For each different DC bias
 - Apply AC signal with fixed amplitude and frequency
 - Measure AC current and calculate impedance
 - Change AC signal frequency and start over
 - Output data interpretation with the model
 - Calculate equivalent admittance of the model
 - Impedance (admittance) at each V and f value
 - For each different DC bias find the model parameters values that allow best matching the measured admittance and the equivalent model admittance at all frequencies
 - Test structure details may play a role
 - Direct (metal) or indirect (AD) access to BE
 - Presence of access impedance element in the model

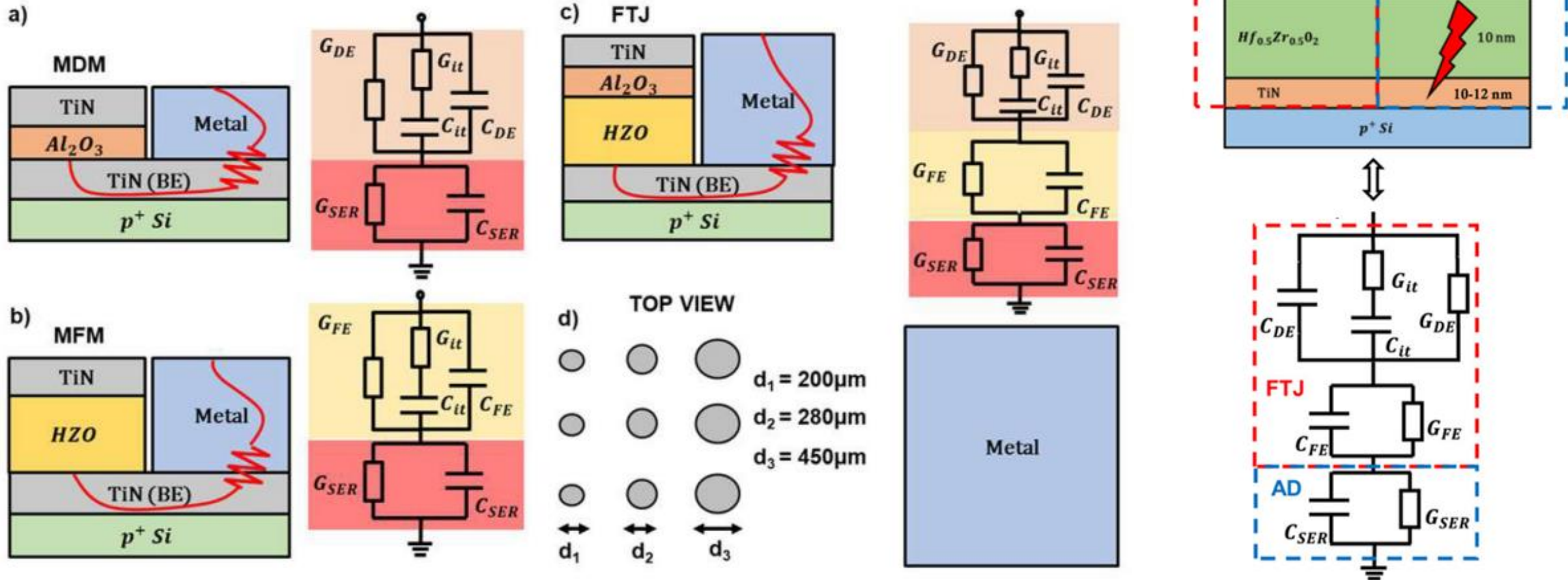


L. Benatti et al., IEEE TDMR, 22 3 (2022)

IMPEDANCE SPECTROSCOPY

FIXIT

- Example for MFM, MDM, MFDM (FTJ) structures with direct/indirect BE access



L. Benatti et al., IEEE TDMR, 22 3 (2022)

L. Benatti et al., IEEE TDMR, 23 3 (2023)



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- Model free parameters must not depend on frequency
 - Frequency dependence can be incorporated using explicit mathematical formulation
 - For instance, 1st-order dielectric permittivity dependence on frequency
- Polar and non-polar composition of ferroelectric can be included
 - Area factor considers the relative abundance of polar vs non polar area
- A few examples where **known** and **free** parameters are highlighted

$$C_{FE} = \epsilon_{FE} \frac{A}{t_{FE}} \text{ with } \epsilon_{FE} = \epsilon_0 [A_f \epsilon_{r,OR} + (1 - A_f) \epsilon_{r,NOR}]$$

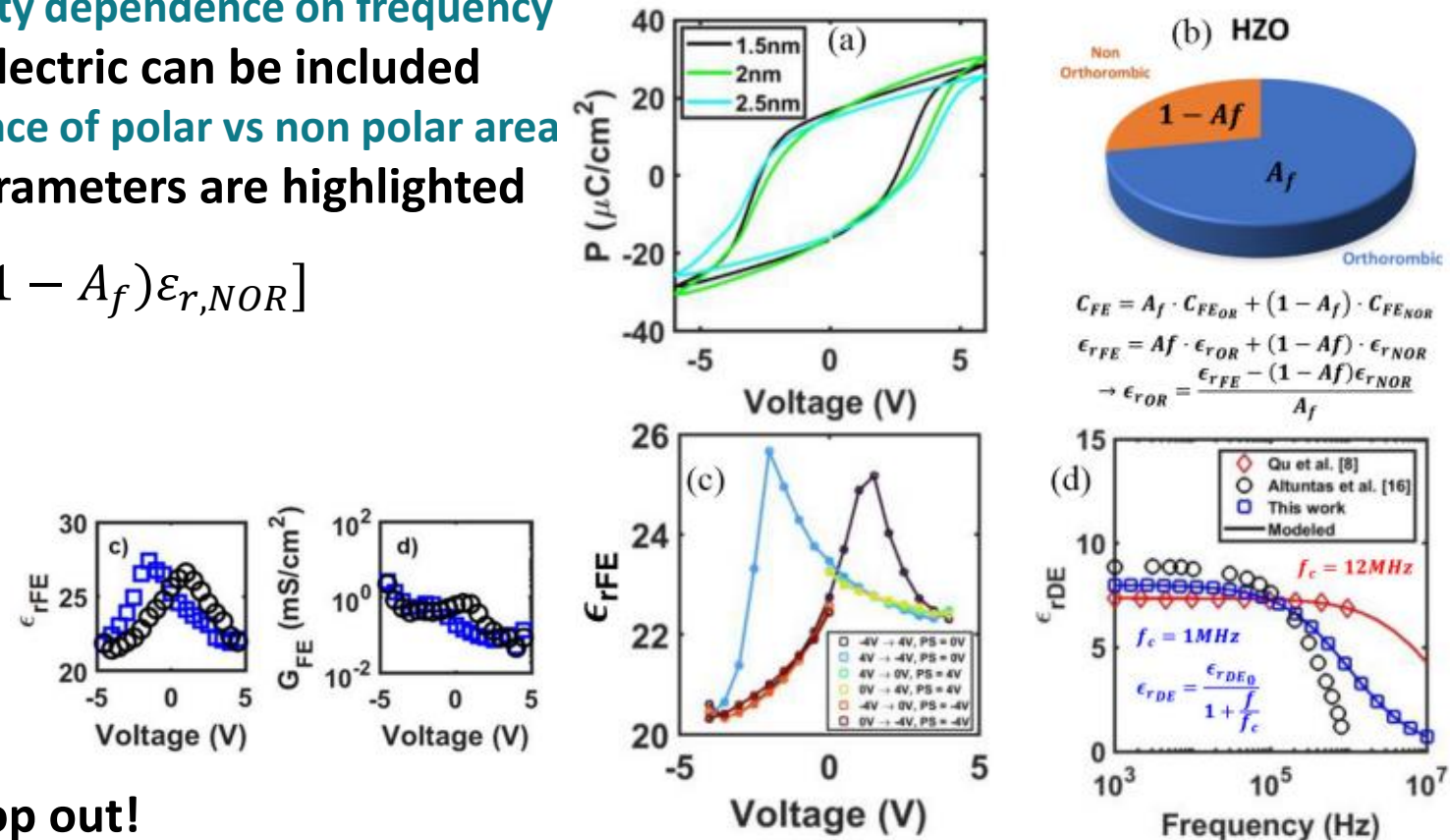
$$C_{DE} = \epsilon_{DE} \frac{A}{t_{DE}} \text{ with } \epsilon_{DE} = \epsilon_0 \frac{\epsilon_{rDE,0}}{1 + \frac{f}{f_c}}$$

G_{DE} expected to be $\propto A$ and $e^{-t_{DE}}$

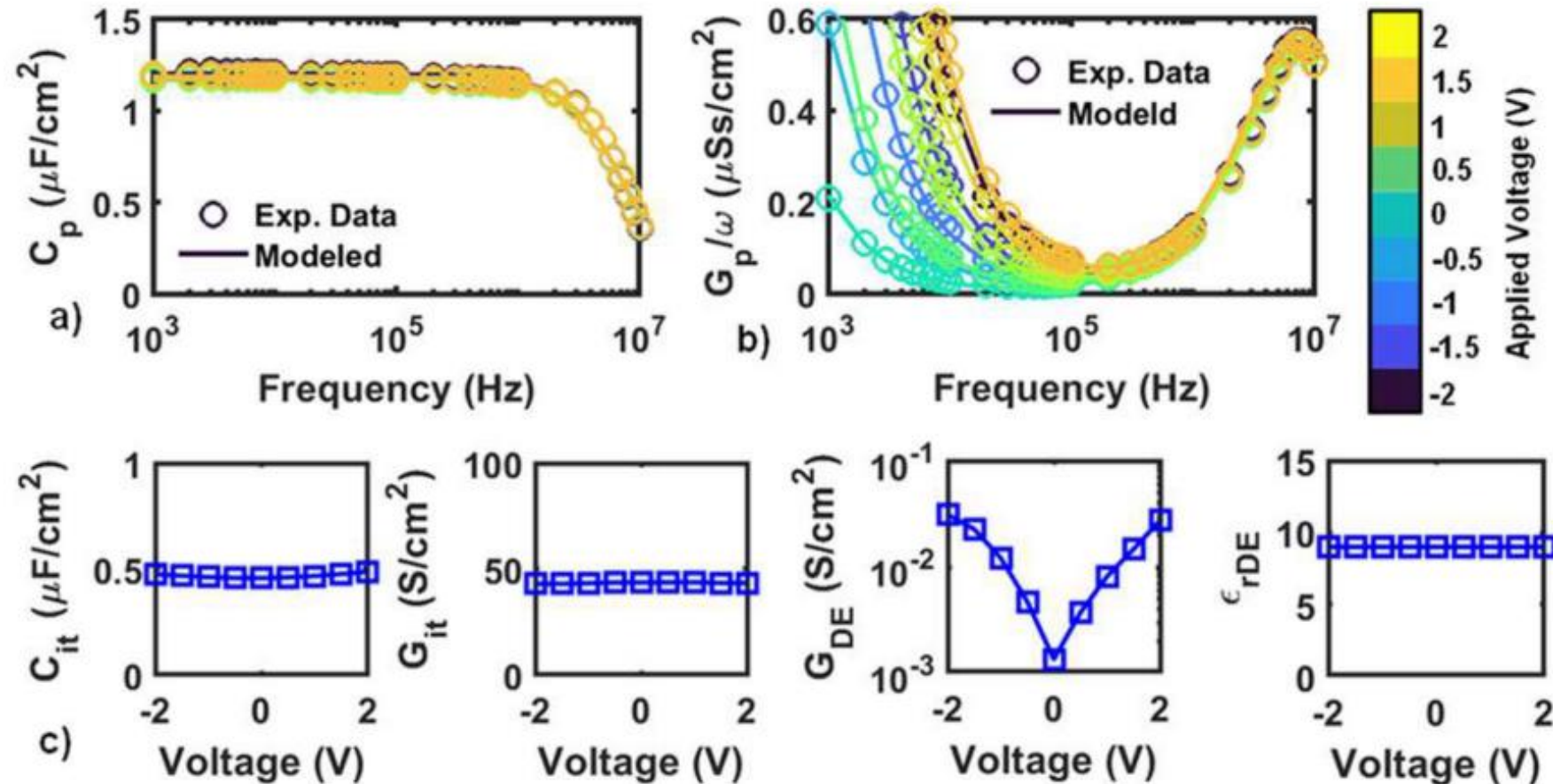
G_{FE} expected to be $\propto A$

- P-dependent ϵ_{FE} and G_{FE} spontaneously pop out!

L. Benatti et al., IEEE TDMR, 22 3 (2022)



- Results for an MDM structure
 - TiN/Al₂O₃ (6nm)/TiN
- Data typically plotted as C_p vs. f and G_p/ω vs. f
- Low-frequency kick in G_p/ω associated with leakage
- High-frequency bump in G_p/ω associated with traps (but access impedance plays a key role here)
- Correct evaluation of dielectric permittivity and leakage profile vs. voltage



L. Benatti et al., IEEE TDMR, 23 3 (2023)

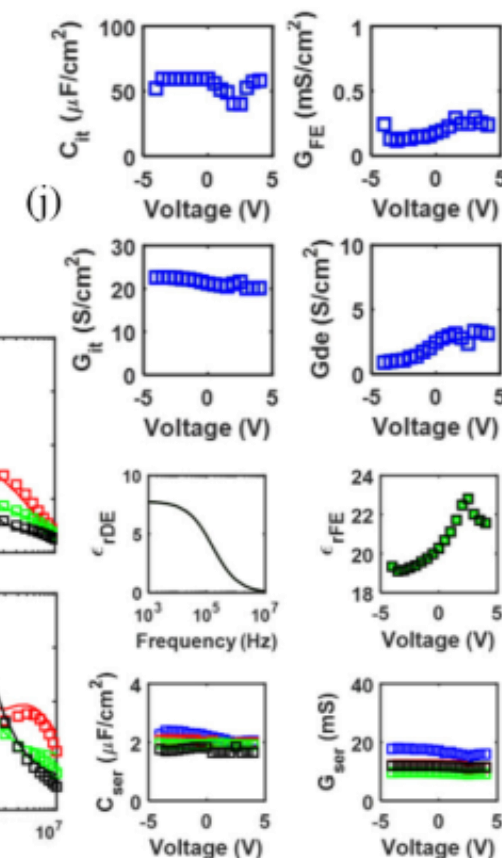
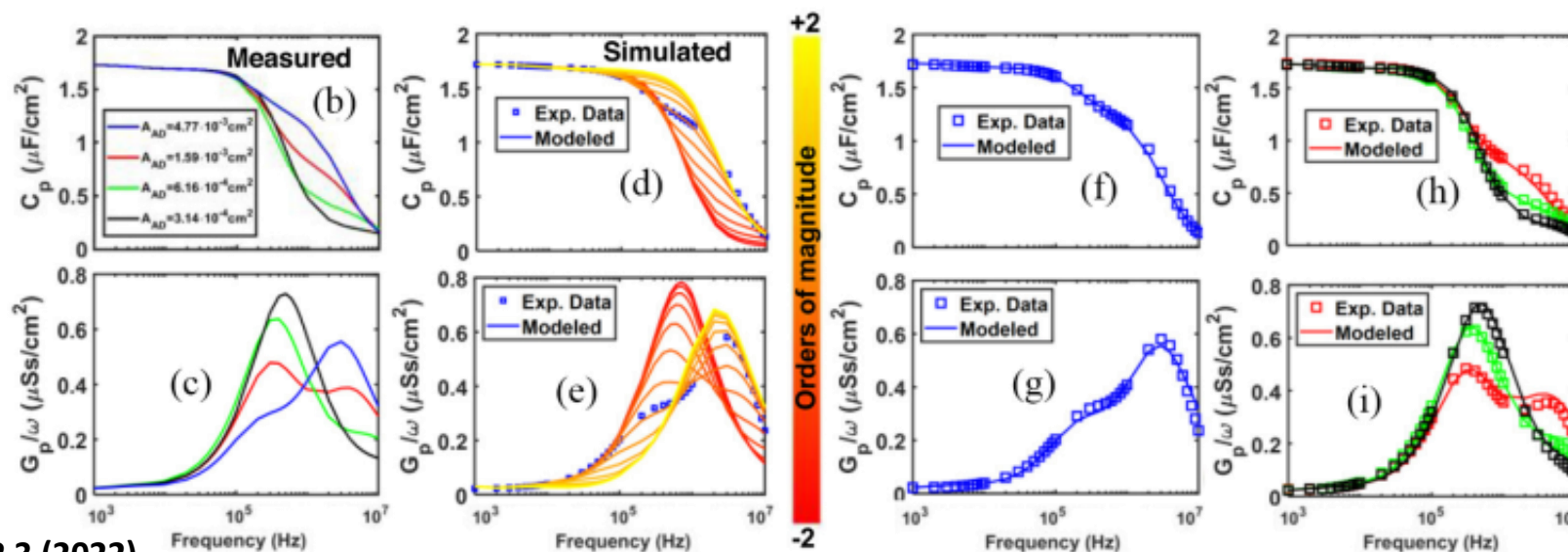
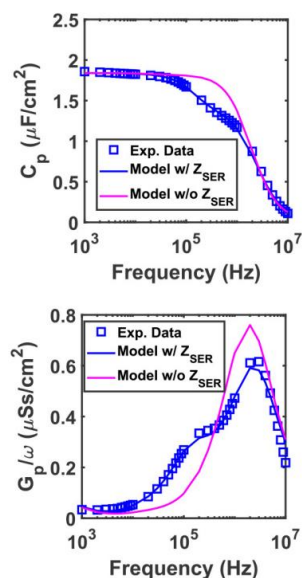
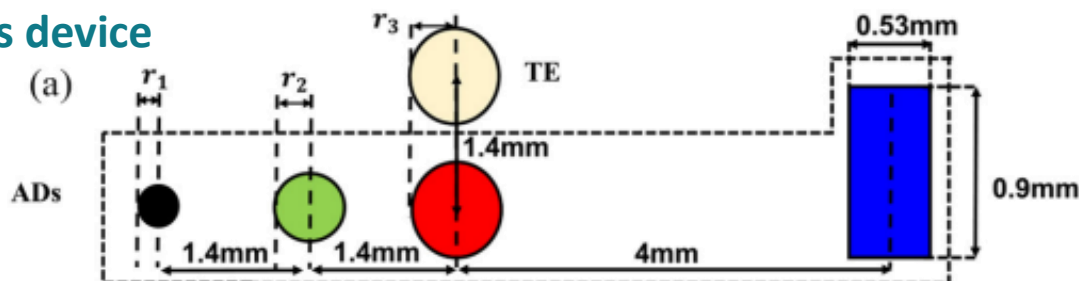


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- Relevant effect of the access impedance

- Results on TiN/Al₂O₃ (1.5nm)/H₂O (10nm)/TiN with different A and access impedance (indirect access)
- C_{SER} compatible with broken access device
- Critical effect on:
 - C_p roll-off
 - G_p/ω kicks

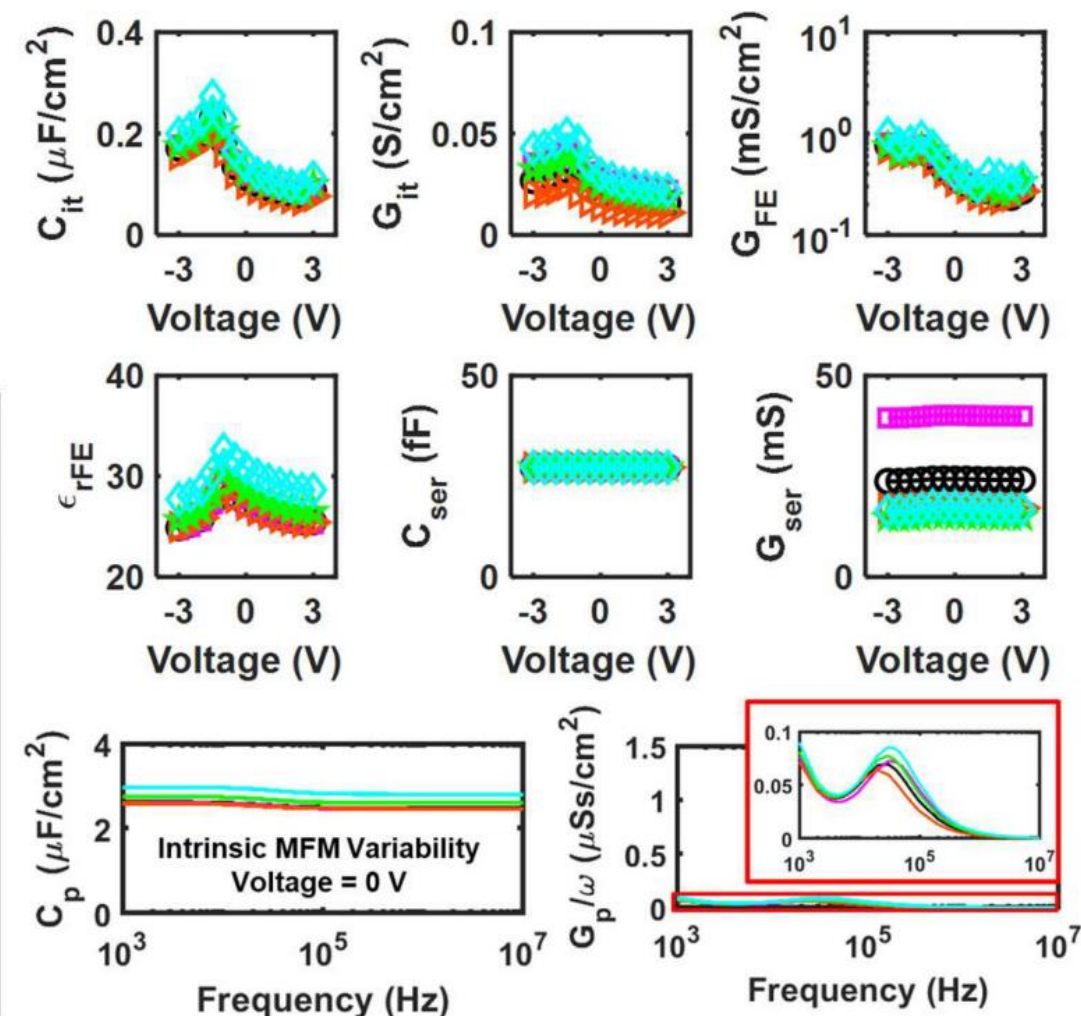
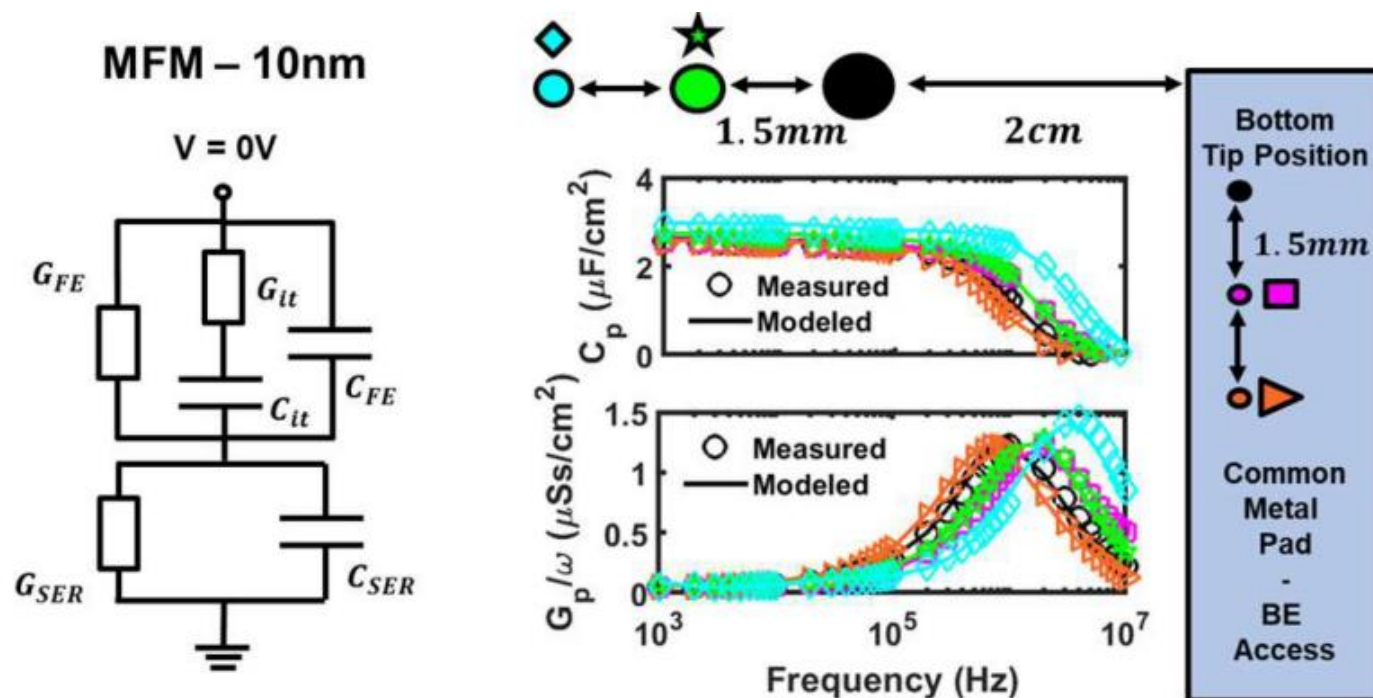
$$\begin{aligned} r_1 &= 100\mu\text{m} \\ r_2 &= 140\mu\text{m} \\ r_3 &= 225\mu\text{m} \end{aligned}$$



IMPEDANCE SPECTROSCOPY

FIXIT

- Results for an MFM structure
 - TiN/HZO (10nm)/TiN
- Excellent match with experiments
- Access to intrinsic device characteristics and variability



L. Benatti et al., IEEE TDMR, 23 3 (2023)



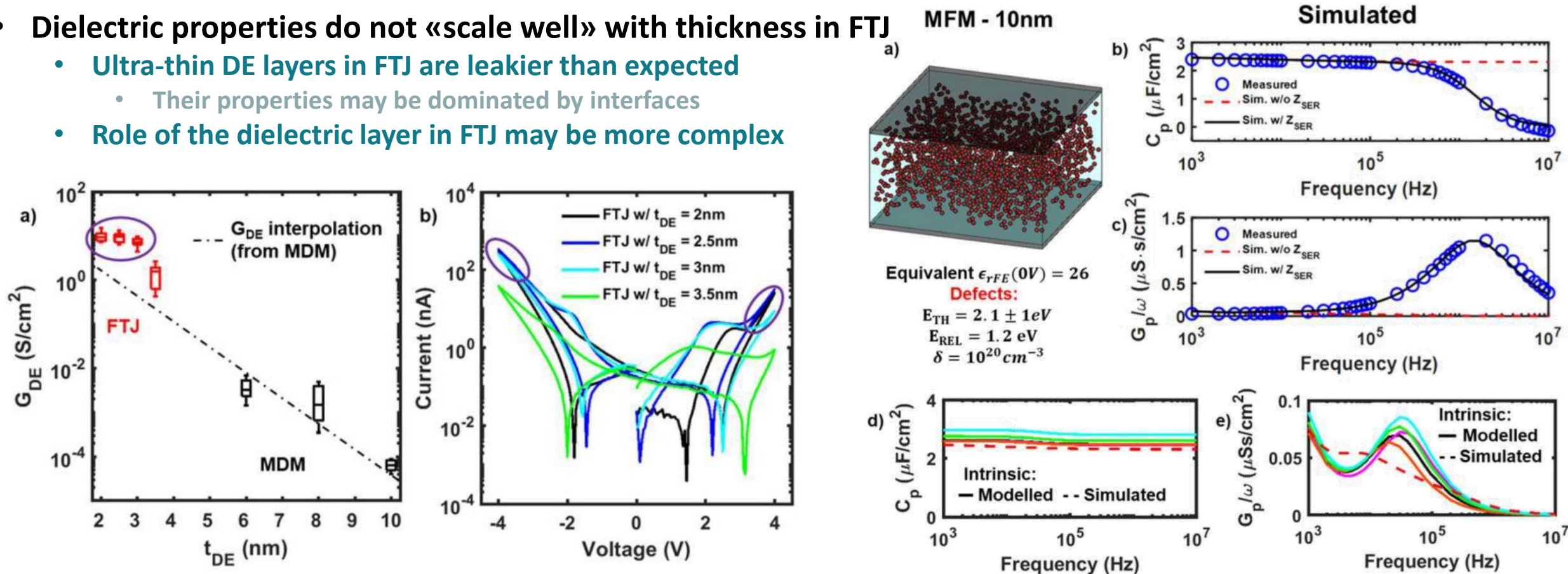
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WHAT CAN WE LEARN FROM IT?

FIXIT

- The effect of series impedance is real
 - Confirmed using physics-based simulations with AMAT's Ginestra
- Dielectric properties do not «scale well» with thickness in FTJ
 - Ultra-thin DE layers in FTJ are leakier than expected
 - Their properties may be dominated by interfaces
 - Role of the dielectric layer in FTJ may be more complex

L. Benatti et al., IEEE TDMR, 23 3 (2023)

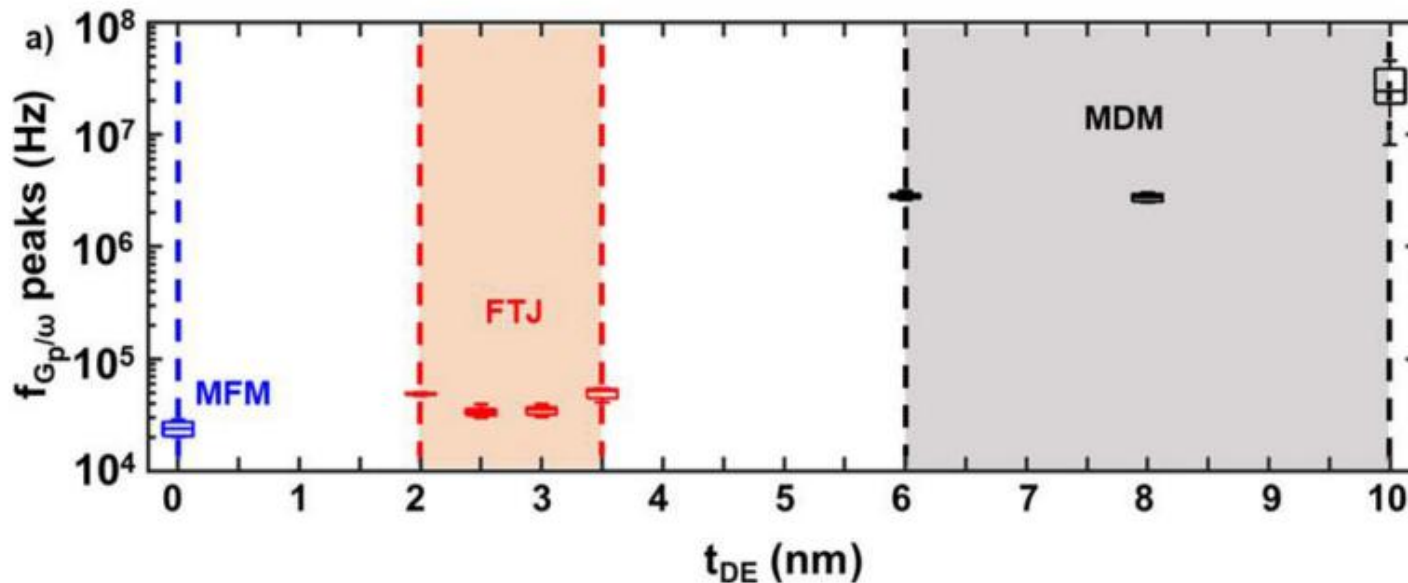


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WHAT CAN WE LEARN FROM IT?

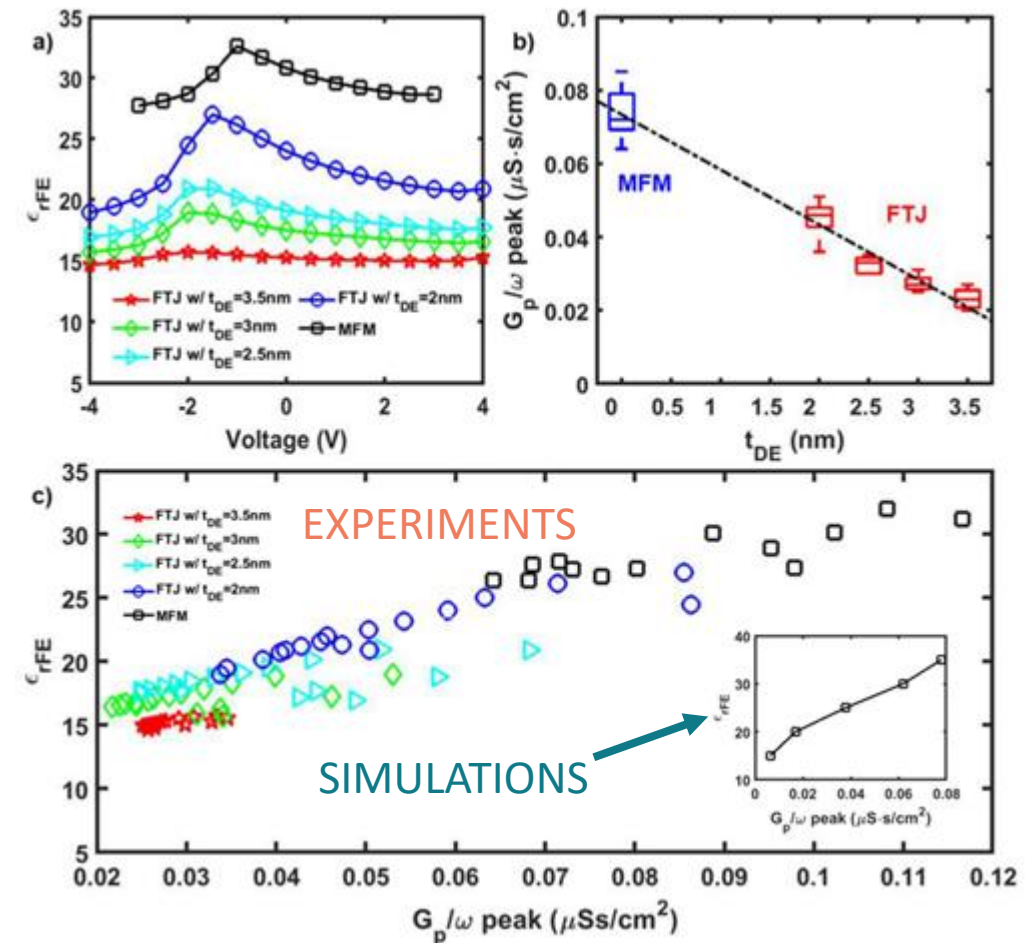
FIXIT

- Interplay between DE and FE properties
 - FE permittivity (polar composition) influenced by DE thickness
 - Strongly relates to G_p/ω peak magnitude
 - Also G_p/ω peak frequency changes with device structure
 - Previously thought to be only related to interface traps*
 - Does a thicker DE inhibit o-FE formation?



* Y. Qu et al., IEEE T-ED, 67 12 (2020)

L. Benatti et al., IEEE TDMR, 23 3 (2023)

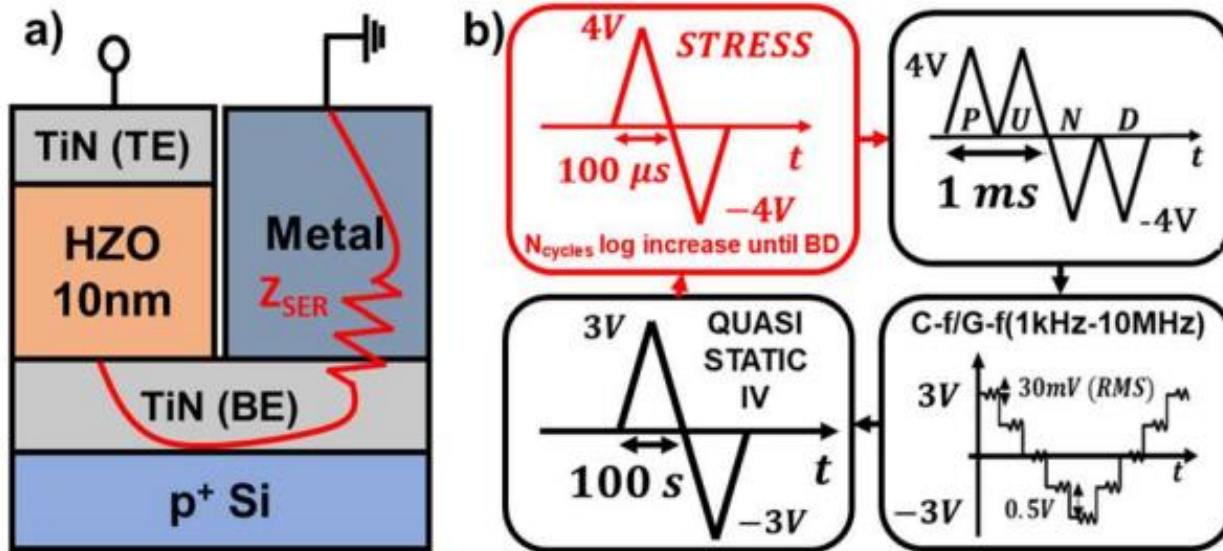


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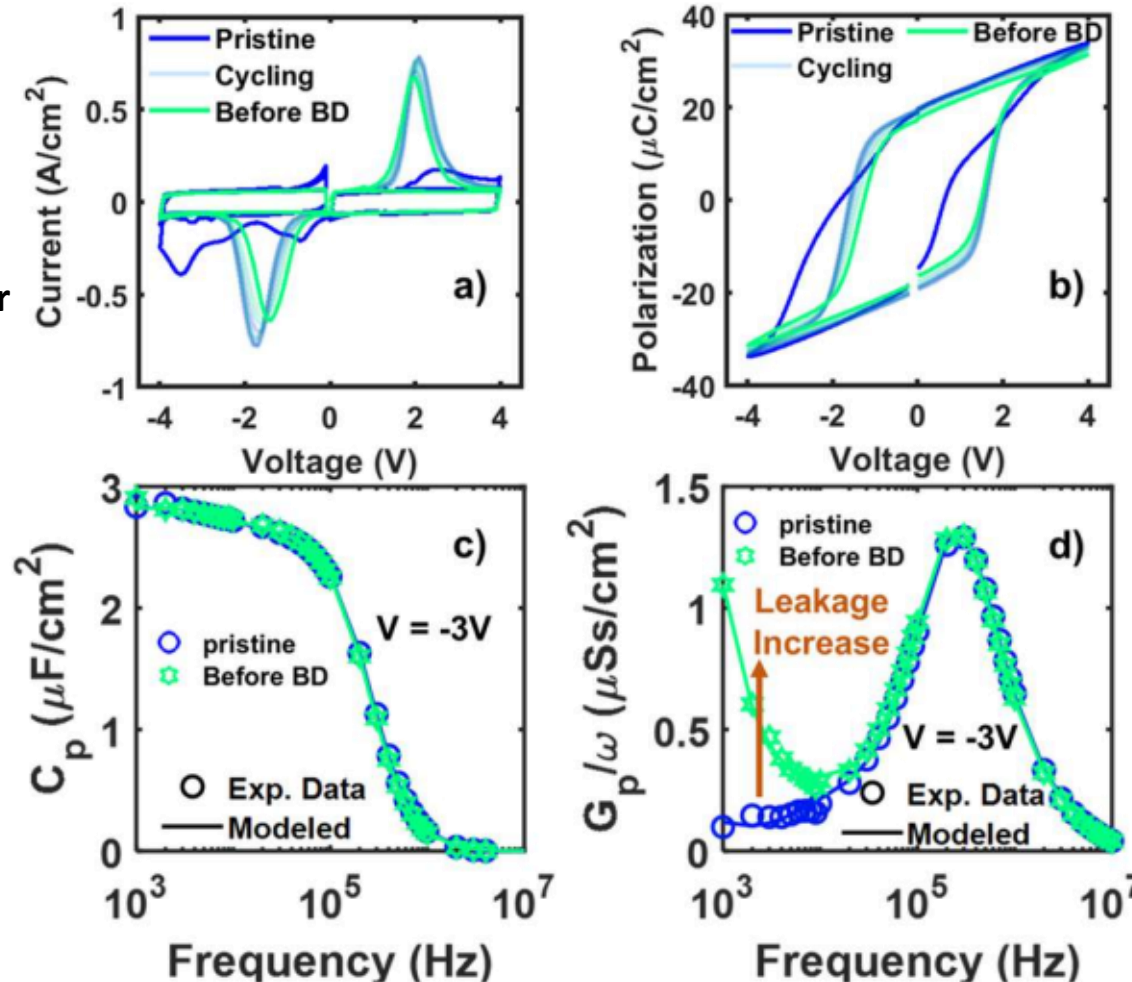
ENDURANCE AND AGING

FIXIT

- Understand endurance failure and aging mechanisms
 - Stress-Measure sequence until device failure
 - Stress = Log-spaced triangular dual voltage waveform(s)
 - Measure = Sequence of PUND, ultra-slow I-V, multi-V C-f/G-f
 - From each measurement extract key indicators
 - PUND → P-V curves, P_R , P_{SAT} , E_C
 - Ultra-slow I-V → Leakage and switching current together
 - Multi-V C-f/G-f → FE and DE properties

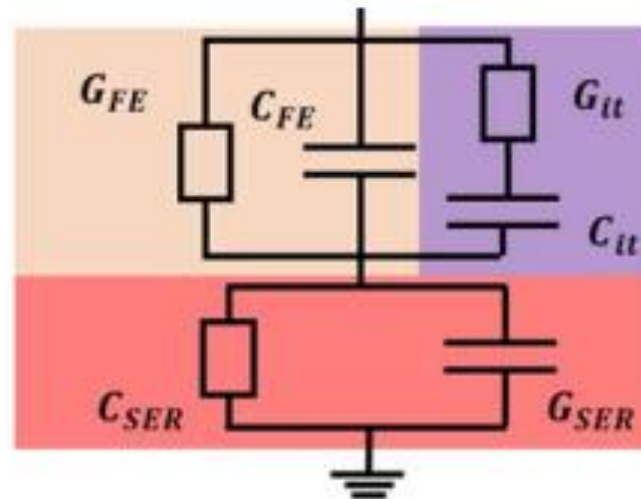
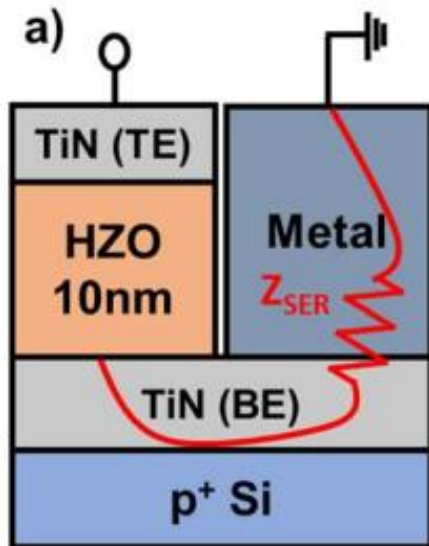


L. Benatti et al., IEEE IRPS (2023)



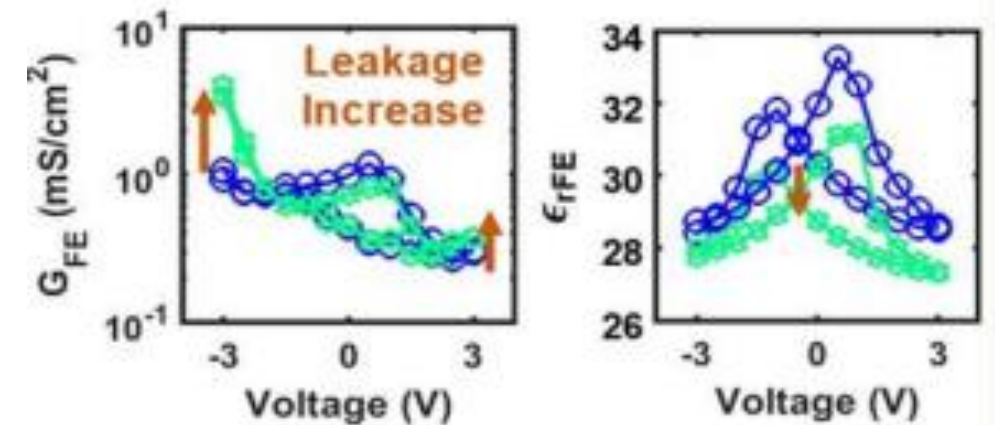
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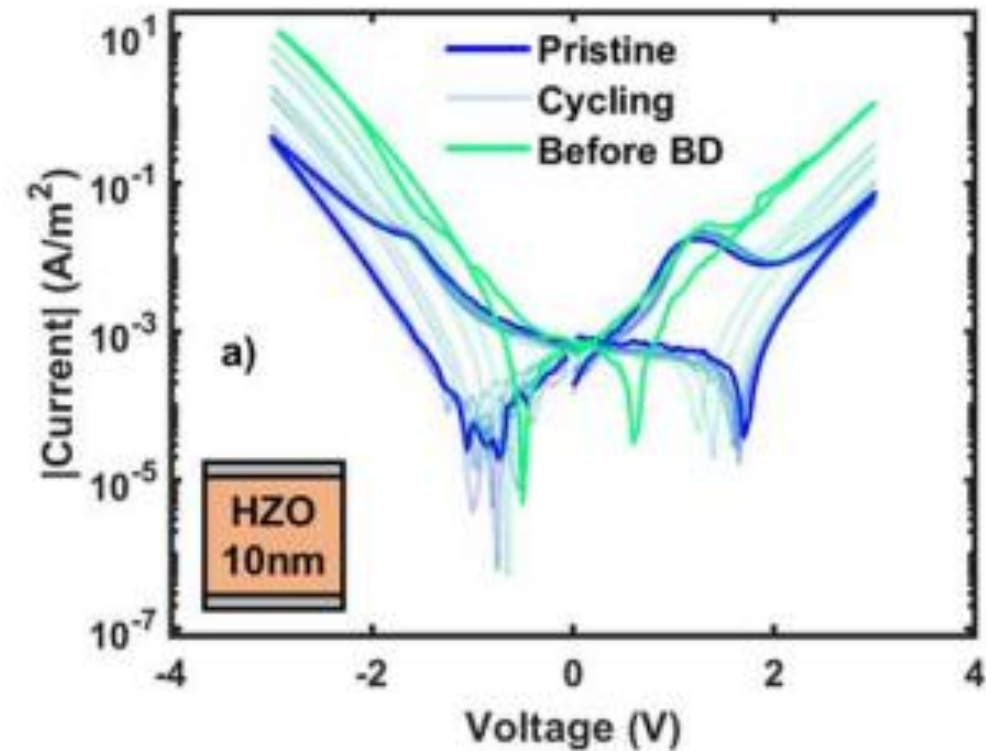
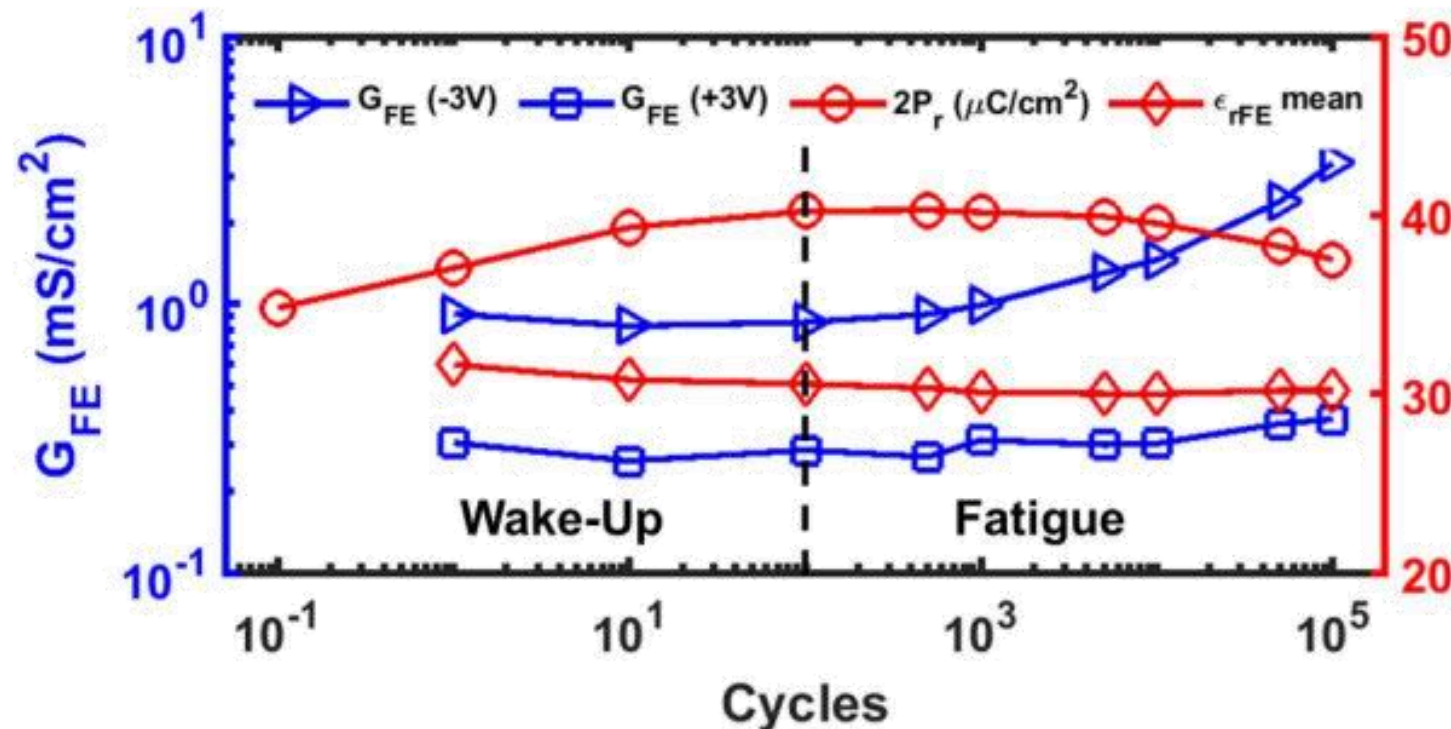
EXAMPLE OF INTERESTING DE/FE PROPERTIES

- Leakage is asymmetric vs. voltage
- Leakage degradation is also asymmetric
- Permittivity degrades as well with aging



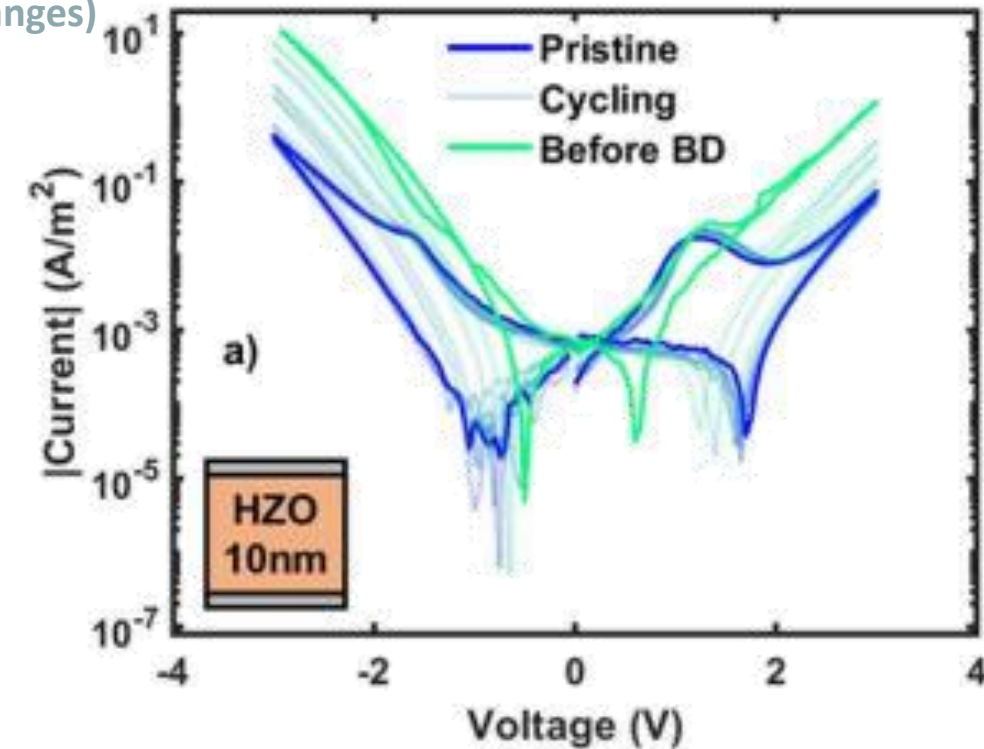
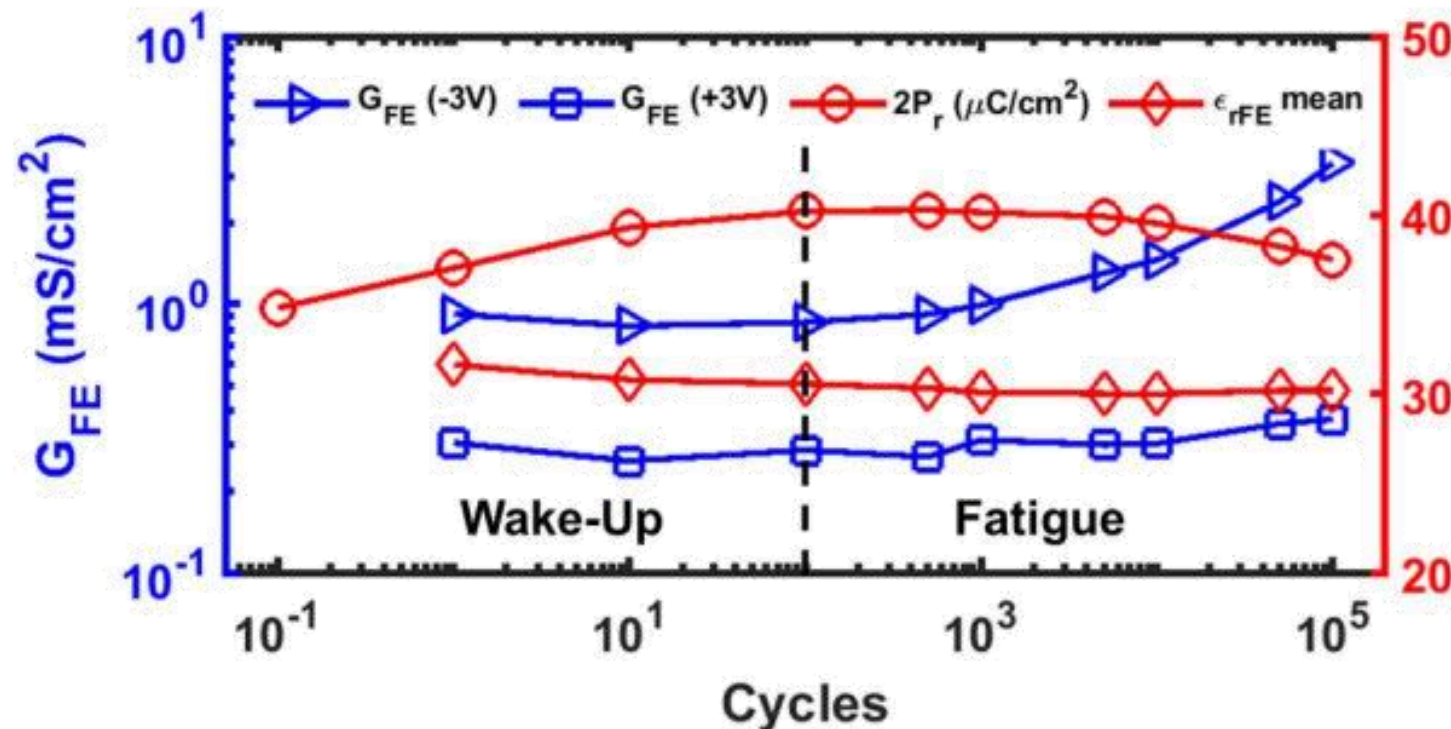
L. Benatti et al., IEEE IRPS (2023)

- Understand endurance failure and aging mechanisms
 - Plot relevant indicators vs. cycles to get insights
 - G_{FE} at extreme voltages ($\pm 3V$ in this example) from multi-V C-f/G-f
 - $2P_R$ from PUND (identify wake-up, fatigue, failure stages)
 - ϵ_{rFE} from multi-V C-f/G-f
 - Entire ultra-slow I-V curves



L. Benatti et al., IEEE IRPS (2023)

- Understand endurance failure and aging mechanisms
 - Plot relevant indicators vs. cycles to get insights
 - Wake-up not associated with massive defect generation
 - Defect generation happens during fatigue and is not symmetric
 - Equivalent FE permittivity degrades during fatigue (compositional changes)

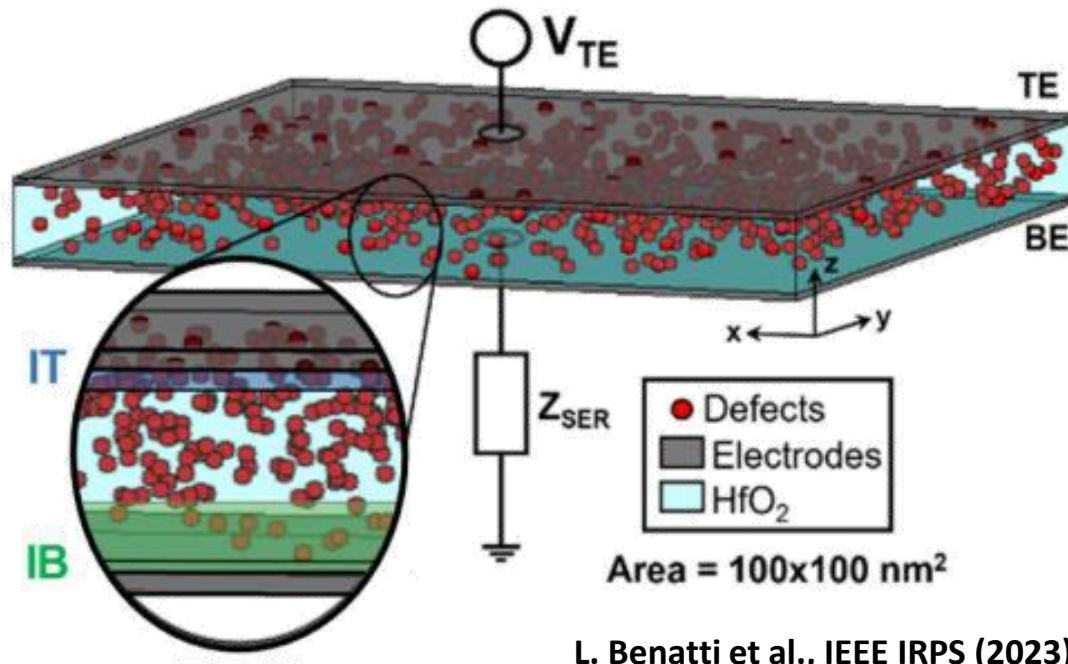


L. Benatti et al., IEEE IRPS (2023)

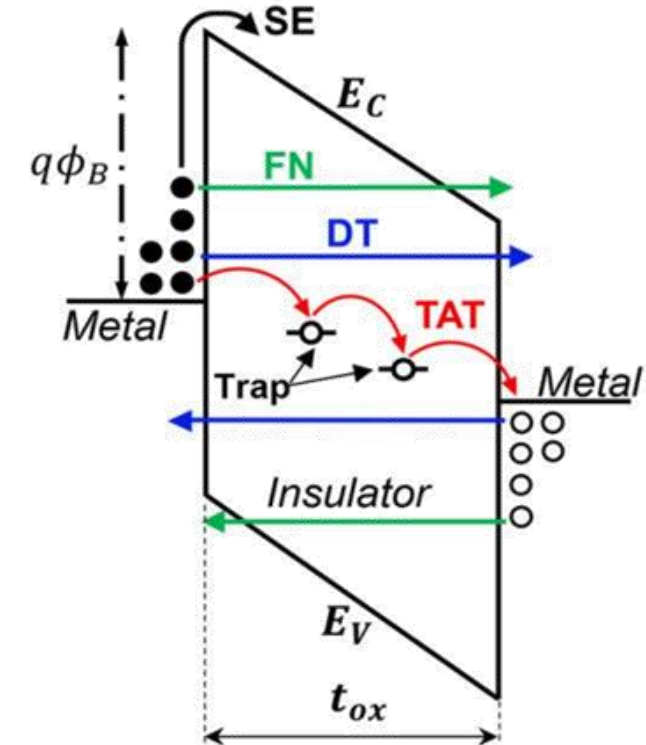
ENDURANCE AND AGING

FIXIT

- Understand endurance failure and aging mechanisms
 - Couple insights with advanced simulations
 - Ginestra simulations include defects and interfacial layers
 - All relevant conduction mechanisms considered
 - Including trap-assisted tunneling with trap-to-trap contribution
 - Series impedance extracted from multi-V C-f/G-f included as well



L. Benatti et al., IEEE IRPS (2023)



SE = Schottky/Thermionic Emission
DT = Direct Tunneling
FN = Fowler-Nordheim Tunneling
TAT = Trap-Assisted Tunneling

S. Vecchi et al., IEEE ESSDERC (2022)



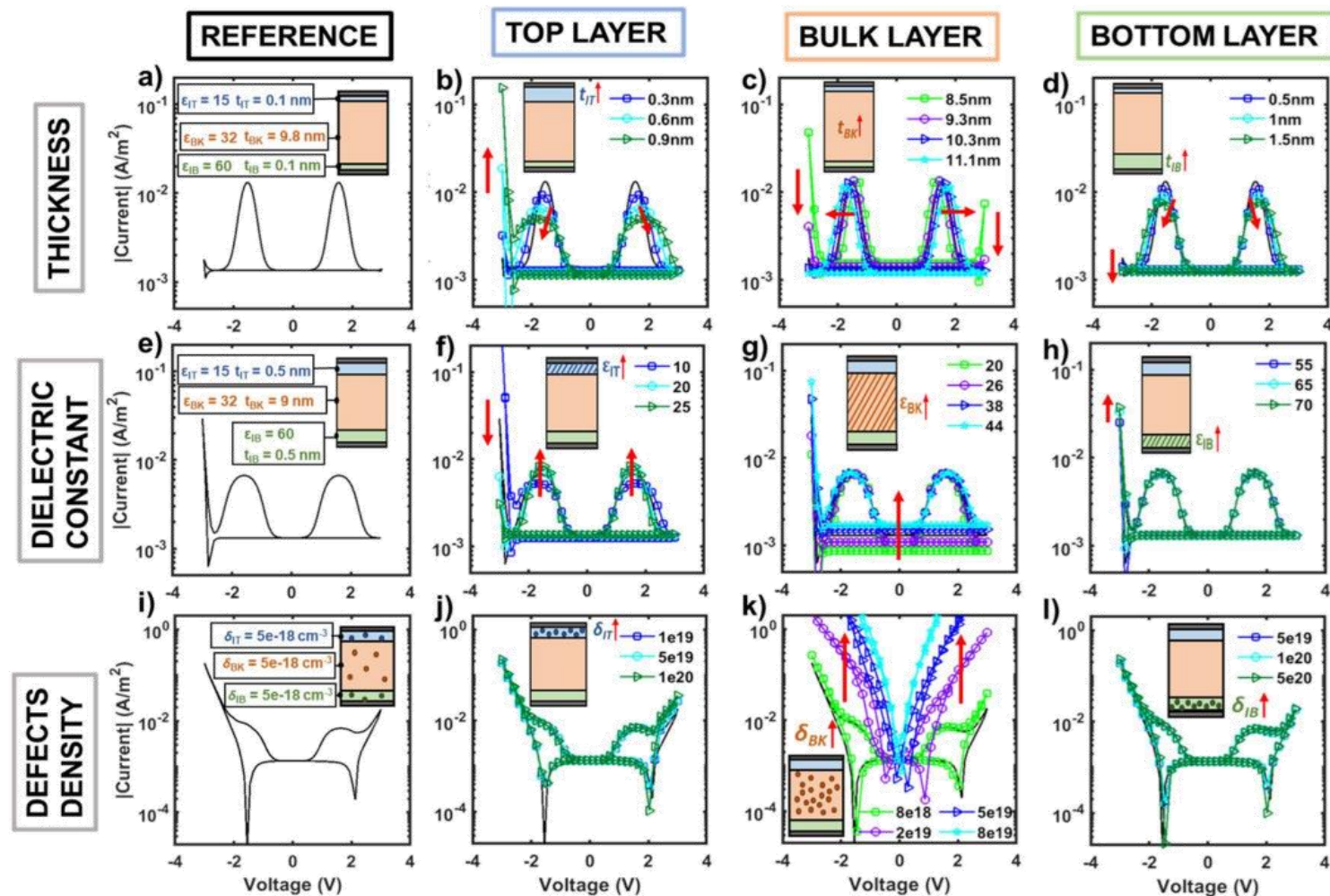
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ENDURANCE AND AGING

FIXIT

- Understand endurance failure and aging mechanisms

- Perform a sensitivity analysis to get hints on key material and defect properties that affect I-V curves
- Defect density in the FE bulk
- Thickness and permittivity of the top interfacial layer



L. Benatti et al., IEEE IRPS (2023)



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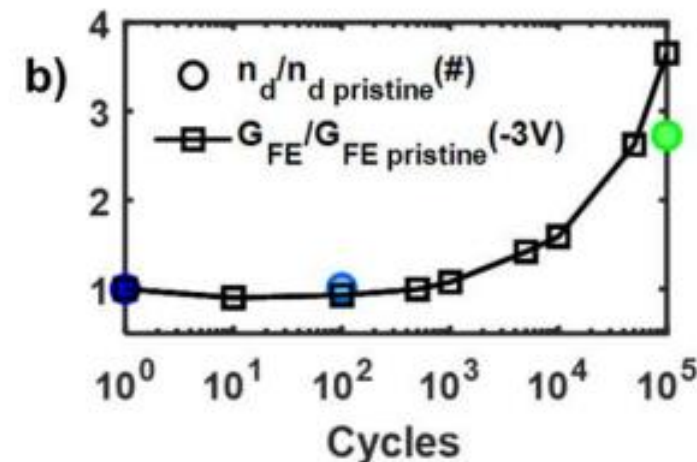
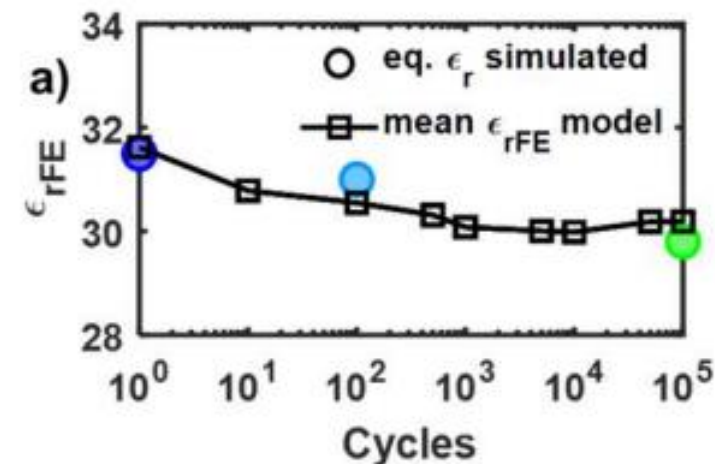
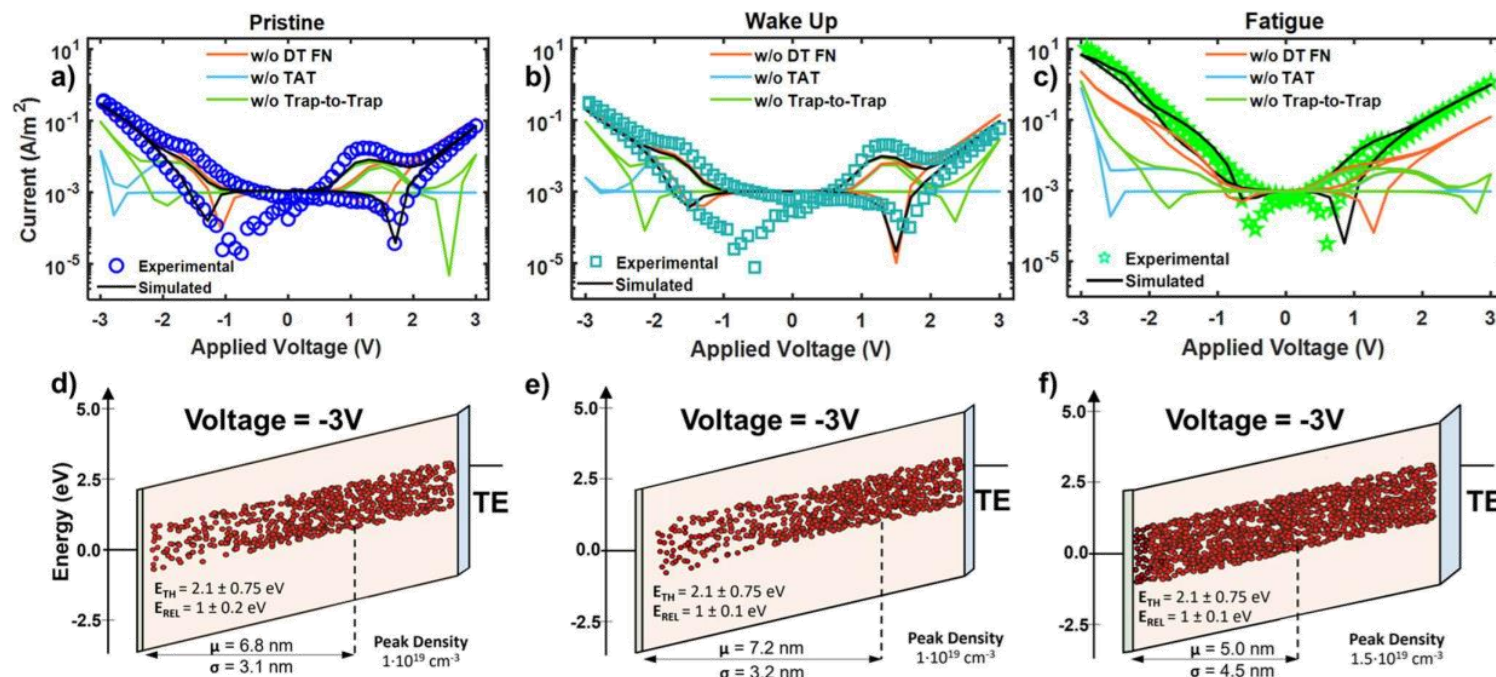
ENDURANCE AND AGING

FIXIT

- Understand endurance failure and aging mechanisms

- Reproducing the ultra-slow I-V curves in simulations requires:

- Including TAT and trap-to-trap contribution in leakage
- Rearranging defect spatial distribution to transition from pristine to wake-up
- Increasing defect density and degrading the top IL to get the fatigued curve
- Top IL thickens at the expenses of the FE layer $\rightarrow$ overall eq. permittivity drops
- Features in-line with what extracted from the multi-V C-f/G-f indicators



L. Benatti et al., IEEE IRPS (2023)



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COMMON THREADS OF RELIABILITY ISSUES **FIXIT**

- All the most relevant reliability issues in ferroelectrics stem from a complex interplay of a few phenomena
 - Granular nature of the ferroelectric material
 - Polar and non-polar grains with different orientations
 - Charge trapping centres (defects)
 - At the interface between materials
 - In the bulk of the different materials
 - Their possible field-temperature-gradient driven motion/re-distribution in the stack
 - Complex depolarization 3D field distribution in the device
 - Due to the field associated to charged defects and the local polarization of the grains
 - Domain pinning/de-pinning due to charge
 - Charge trapping/de-trapping influenced by grain polarization
 - Interface(s) degradation/thickening/thinning and compositional change
 - Phase changes in the ferroelectric (transitions between polar and non-polar)
 - Defects generation due to applied/internal field and charge injection
- A VERY HARD MATTER! Requires sophisticated simulations, dedicated experiments, careful interpretation!
- There's plenty of room at the bottom (of reliability studies in ferroelectrics)

